

SEM Basics

Spectral
Solutions



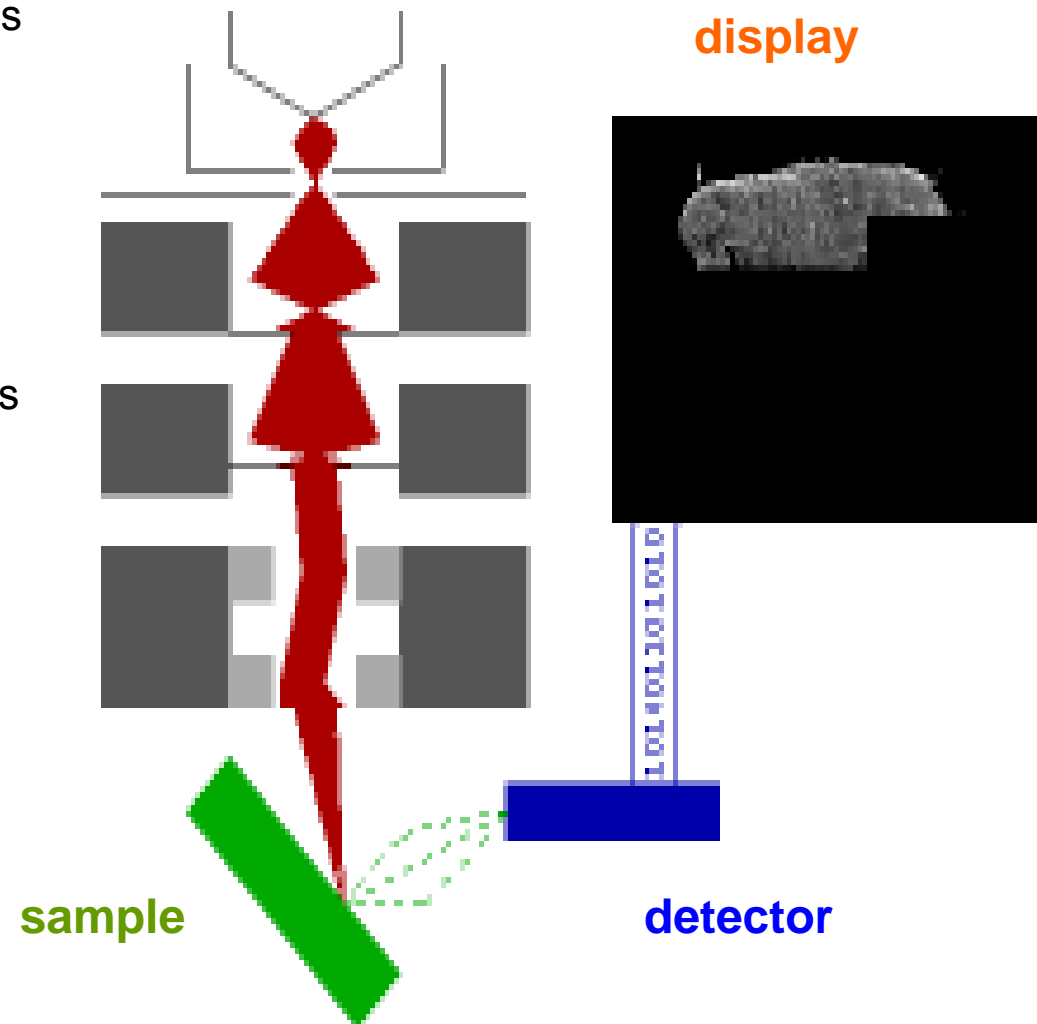
Mats Eriksson
Spectral Solutions

Agenda

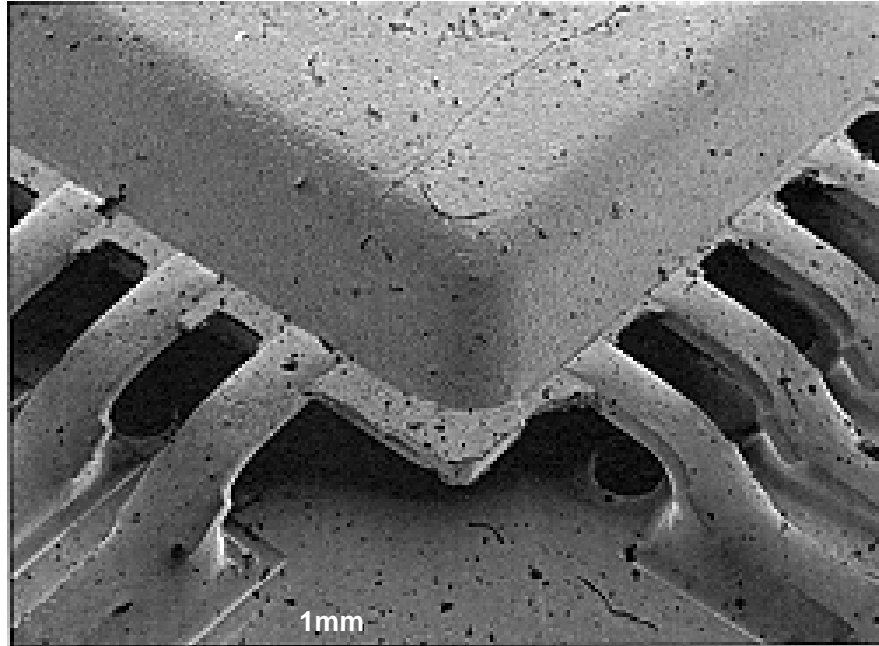
- Why SEM ?
- How does it work ?
- Sampling
- Electron sources and optics
- Electron and sample interaction
- Contrast mechanisms
- Interaction volume
- Imaging problems
- Astigmatism
- Variable pressure
- X-ray microanalysis

How the SEM works

- A finely focused beam of electrons is moved across the specimen one point at a time
- These stimulate electron emission which travels to a detector where they are collected and amplified
- The image is assembled - like a mosaic - from the million or so pixels sequentially examined by the beam and presented on a computer screen



Macroscale to meso-scale...

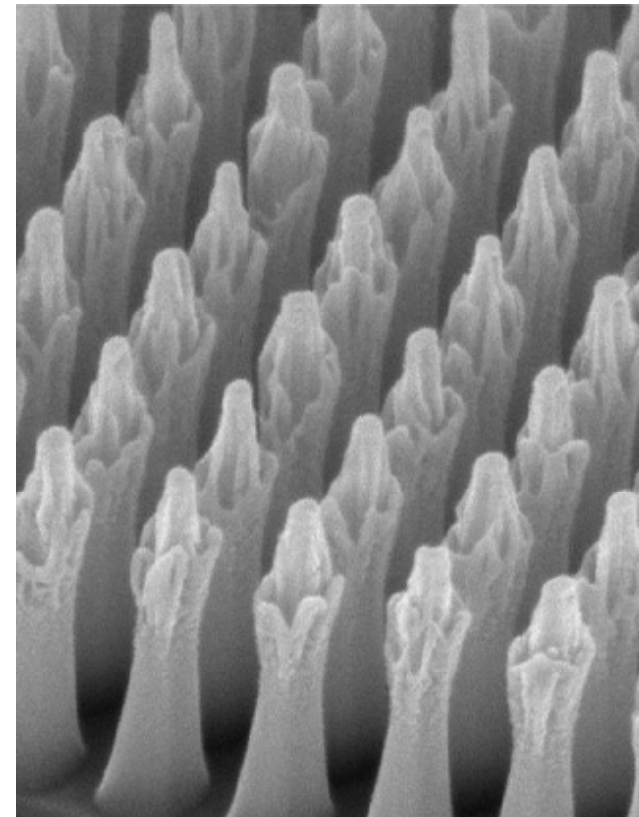


Packaged microchip ready to ship
– Field of View 5mm S3400

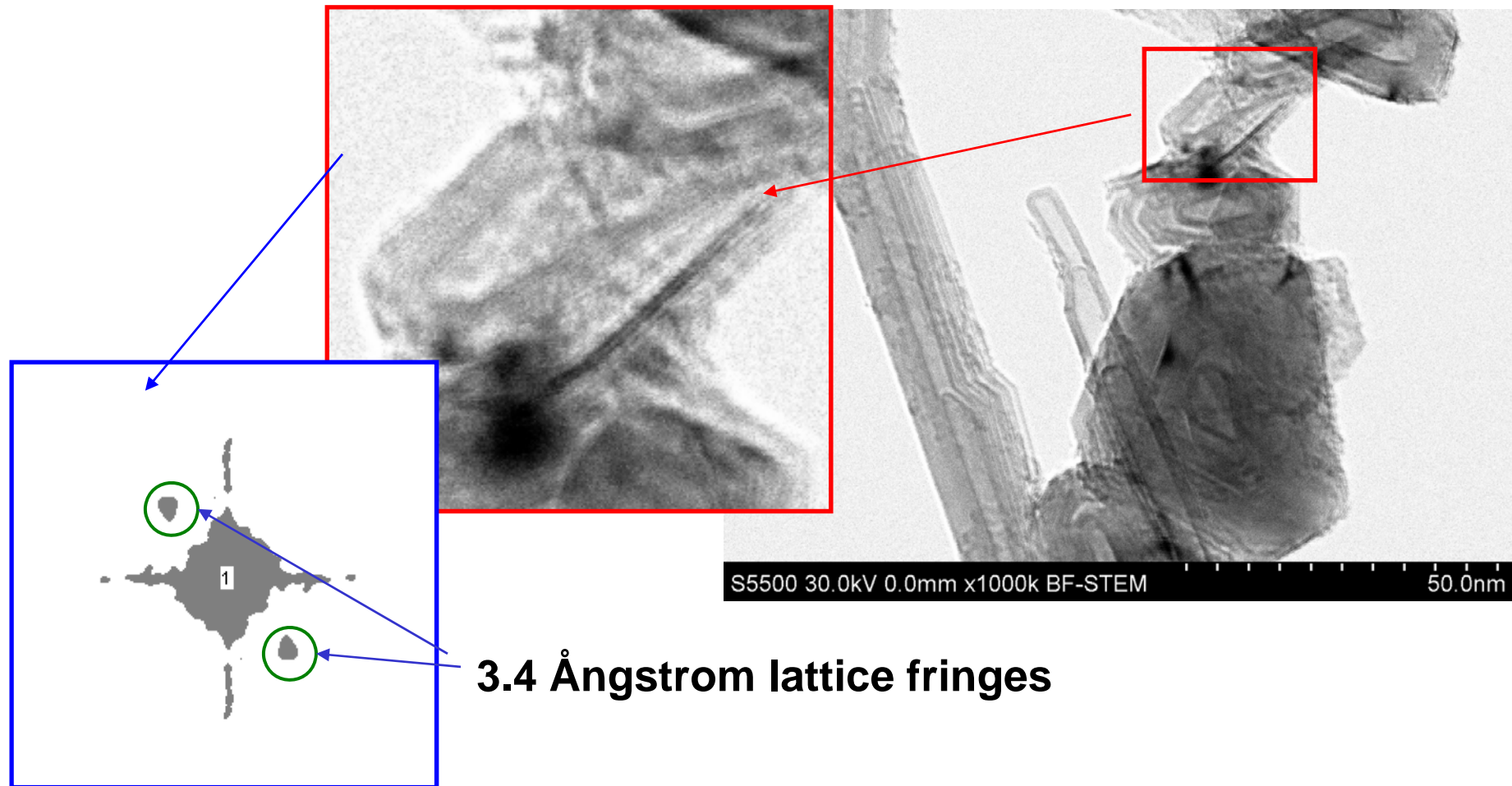
Imaging in context - low and high magnification for
problem solving and flexibility of imaging mode

**Ordered array of
Carbon NanoRods on
Si Field of view 1 mm**

S4700

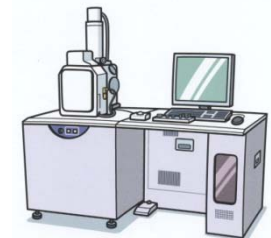
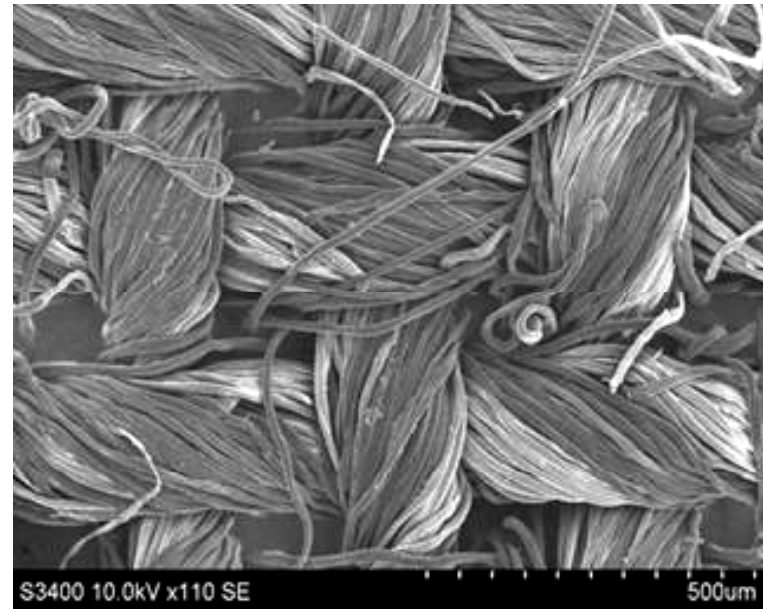
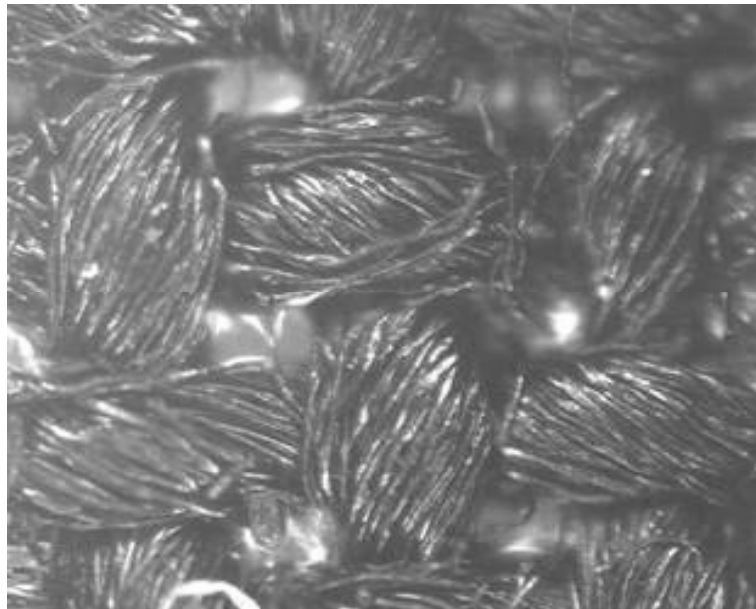


....To true nanoscale

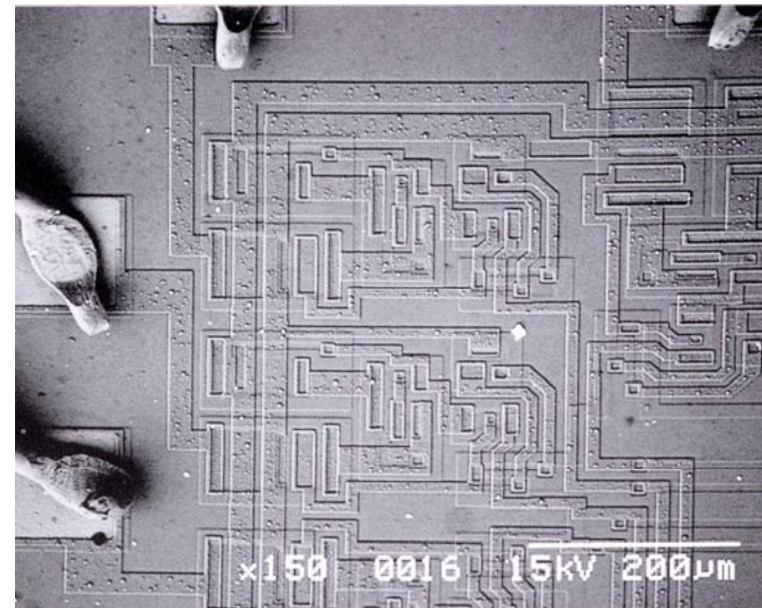
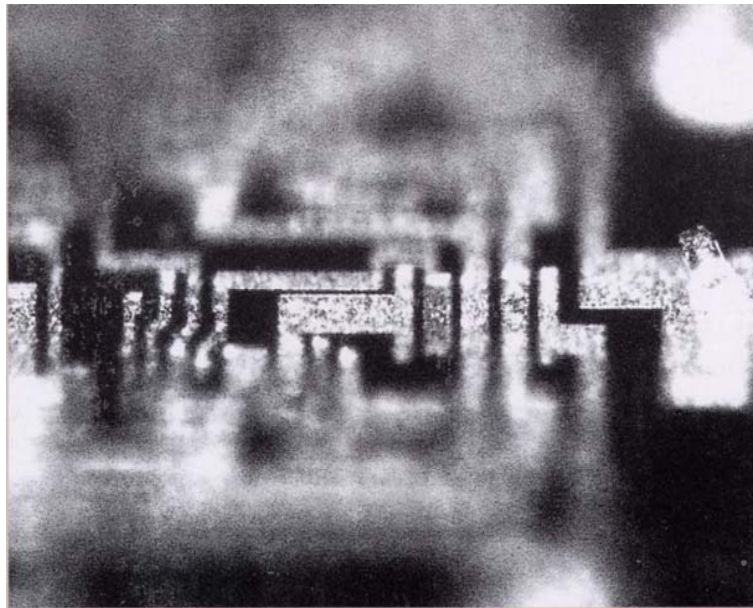


SMART FFT analysis

What is the SEM?



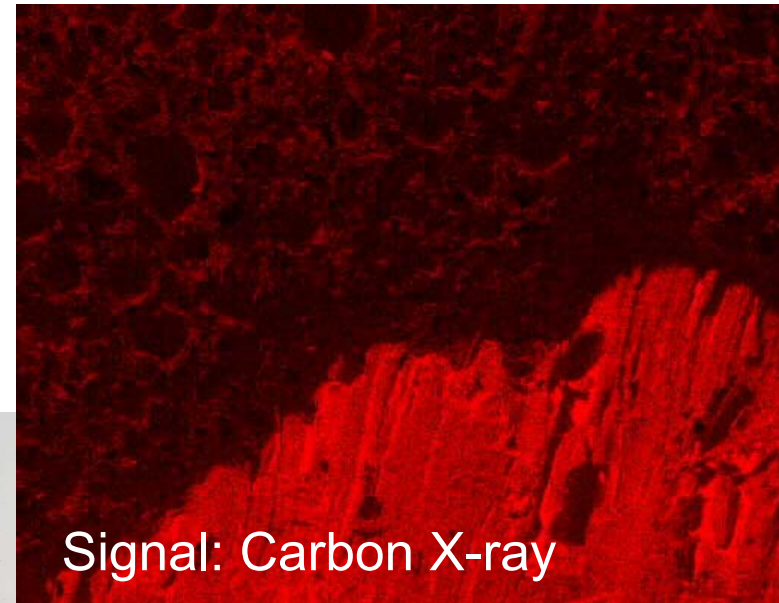
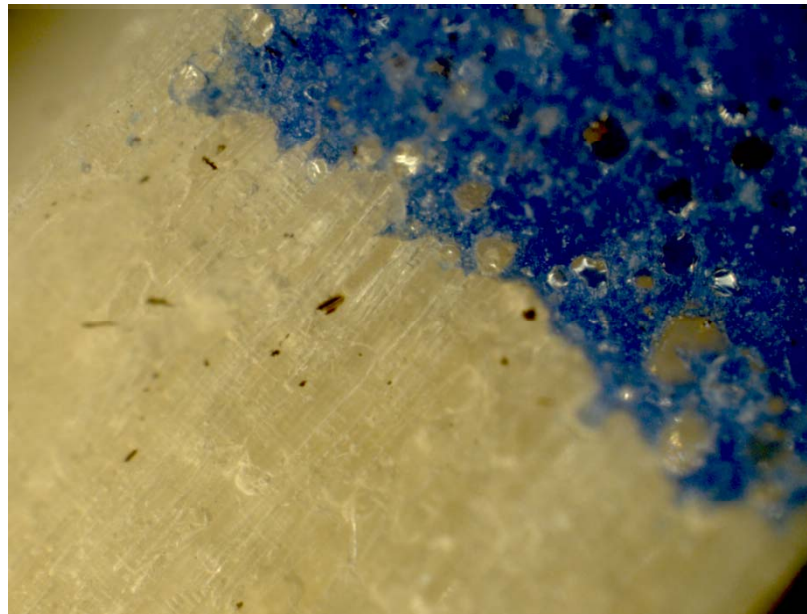
What is the SEM?



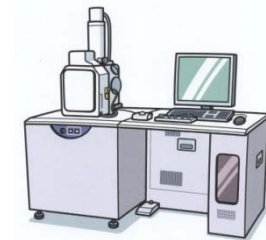
Better depth of focus



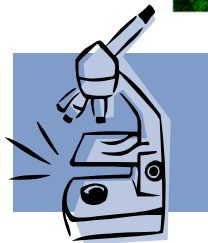
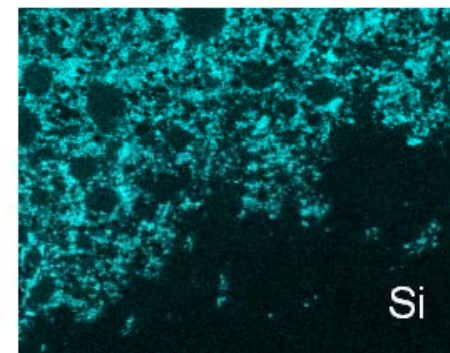
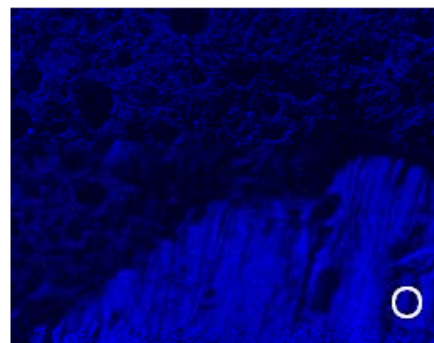
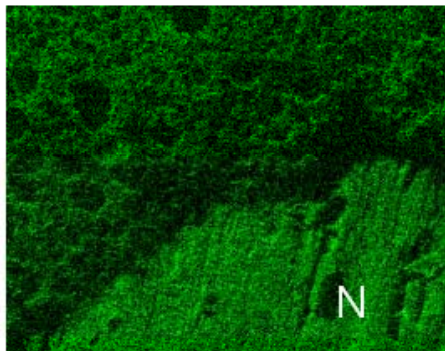
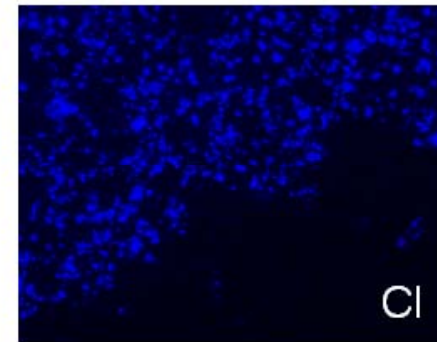
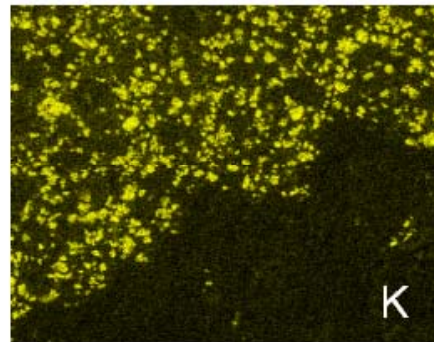
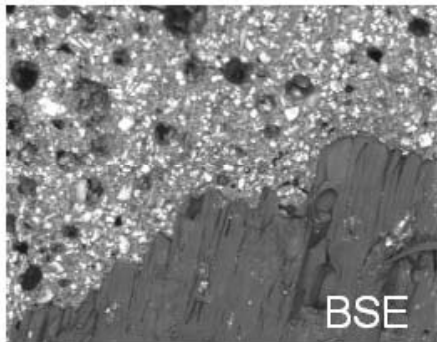
What is the SEM?



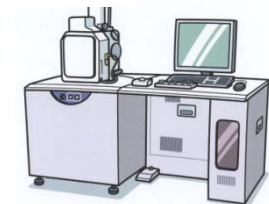
Better depth of focus



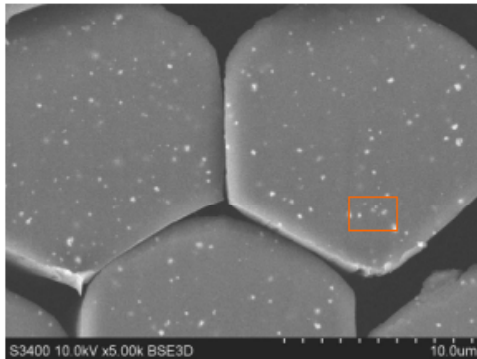
What is the SEM?



Possibility for chemical analysis

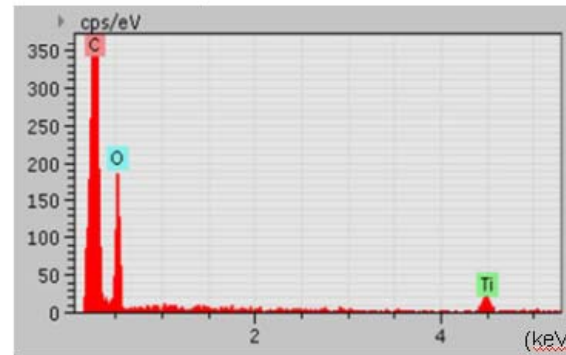


What is the SEM?

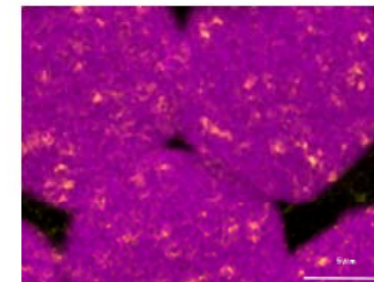


Backscattered electron image
(× 5,000 magnification)

The cross-sectional structure of the fiber was observed with a backscattered electron detector. This permits confirmation of how the white particles are dispersed in the fiber.



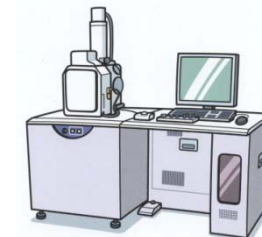
□ X-ray spectrum of area enclosed in rectangle above



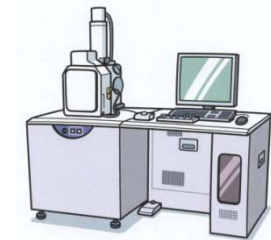
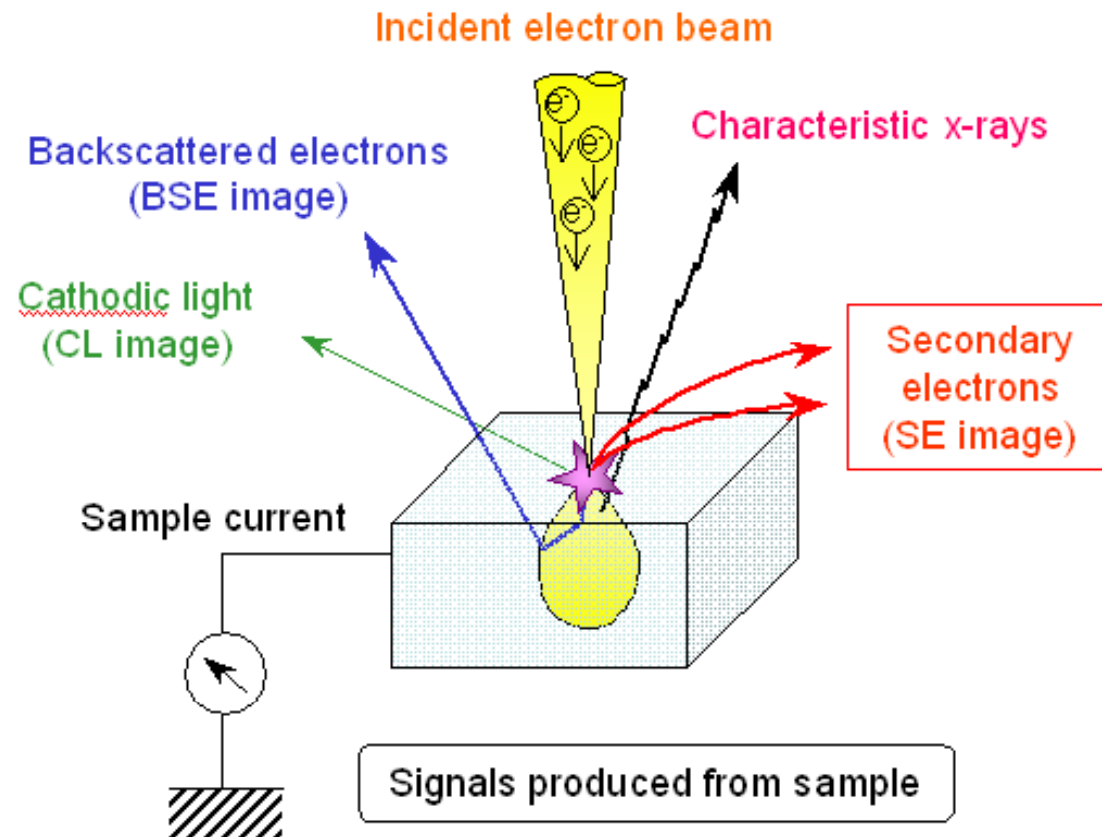
□ X-ray mapping image of C and Ti










Possibility for chemical analysis



What is the SEM?



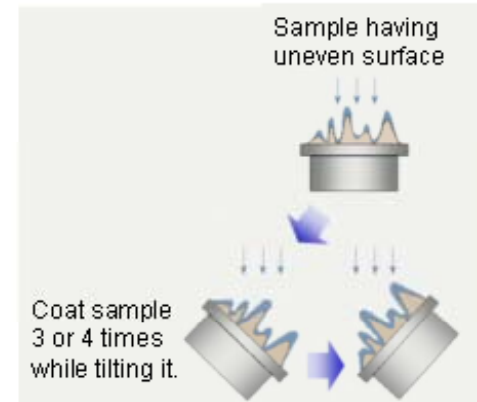
Sampling

							
Name	Specimen stub	Double sided Carbon Tape	Conducting Graphite Paint	Tweezers	Wafer Tweezers	Blower	Diamond Scribing Pen

Sampling



Magnetron sputtering device



Coating of sample having uneven surface

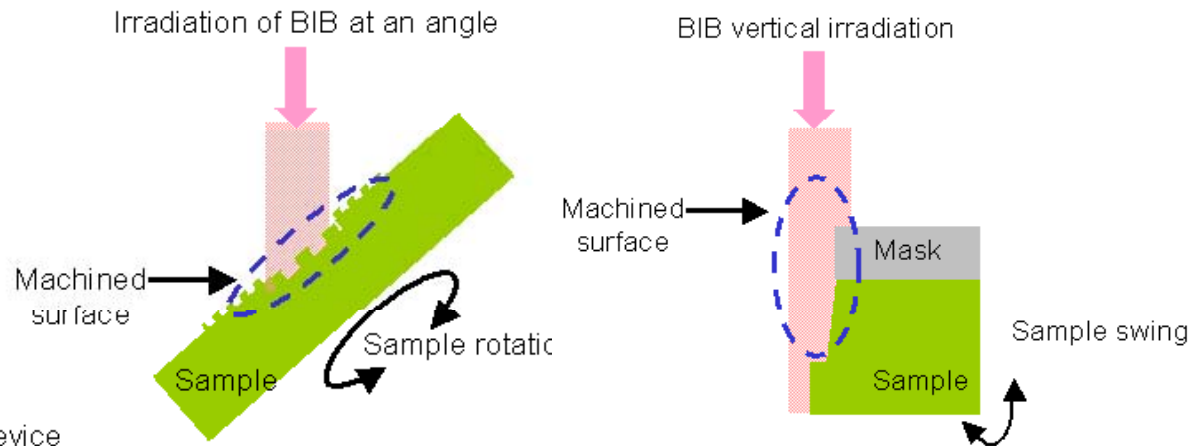
(1) Purposes of coating

- To make the sample surface conductive (prevention of charge-up)
- To increase the production rate of secondary electrons (increase image information)
- To prevent damage to sample

Sampling



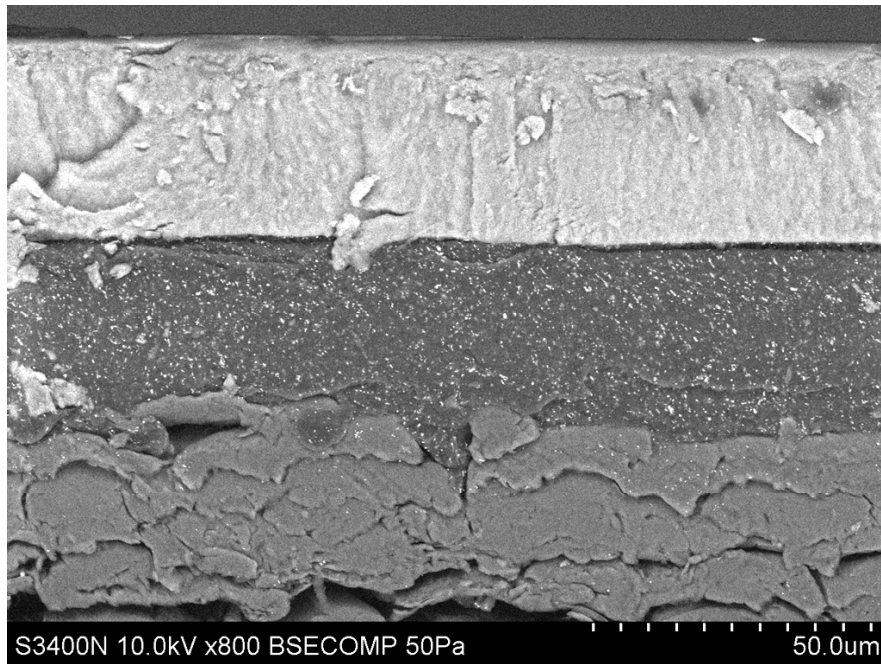
Outer view of IM-3000 ion milling device



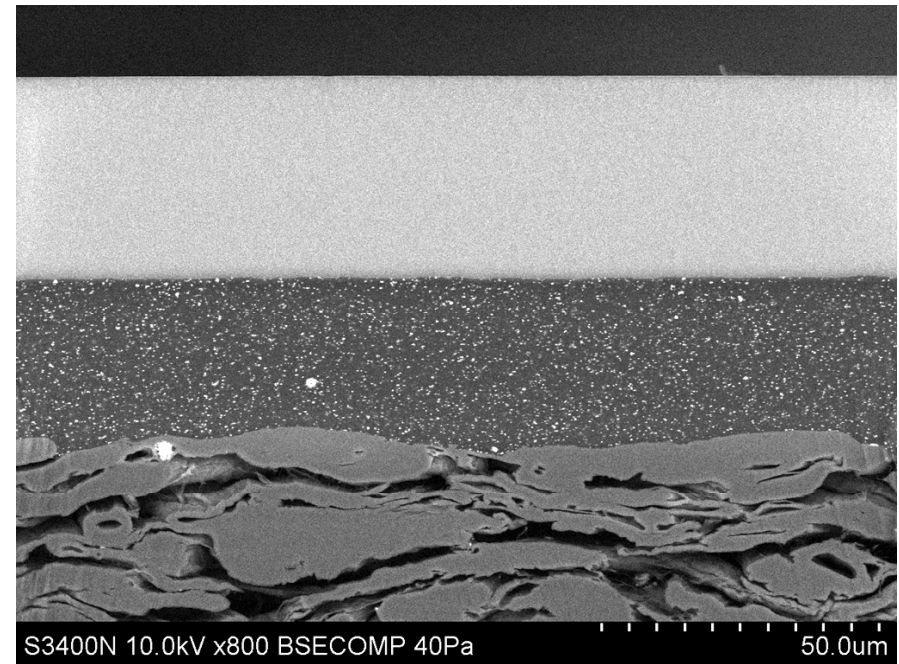
(1) Purposes of BIB (Broad Ion Beam) milling:

- To make the sample surface flat for EDX and EBSD analysis
- To eliminate oxid films or contamination, to enhance crystal orientation contrast
- To prepare “stressfree” a proper cross section of complex compound materials

Sampling



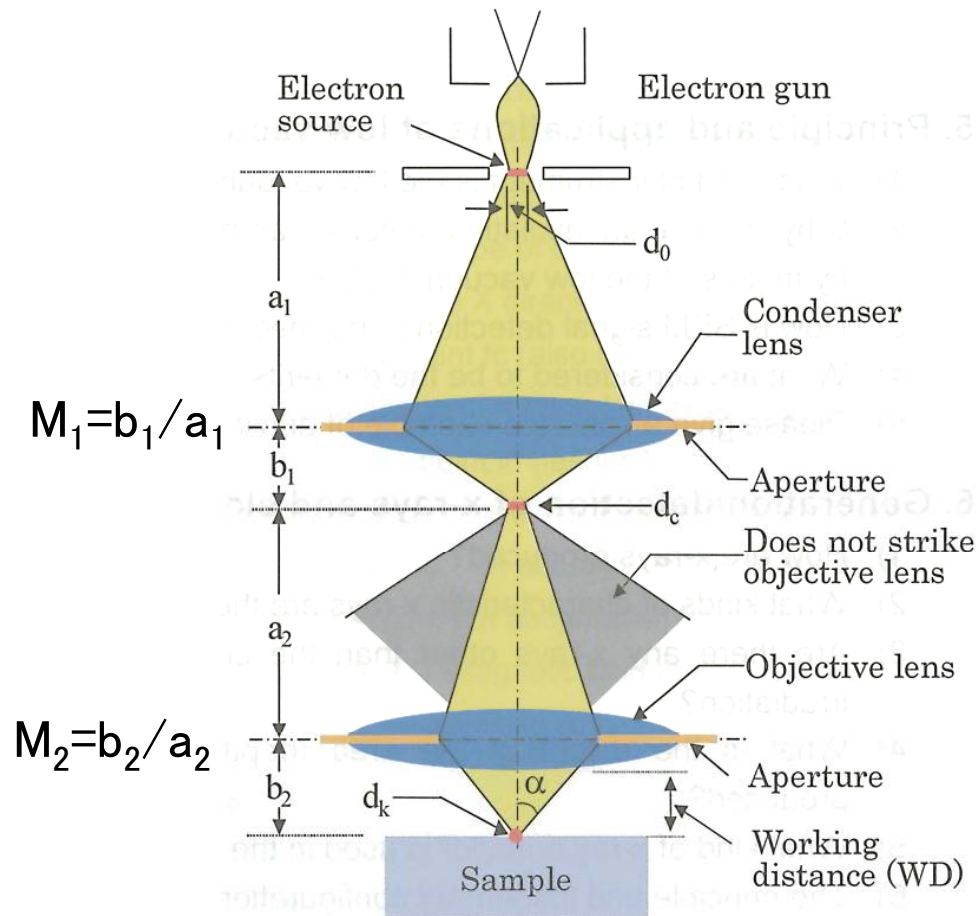
(a) BSE image after razor cutting



(b) After Milling (BSE Image)

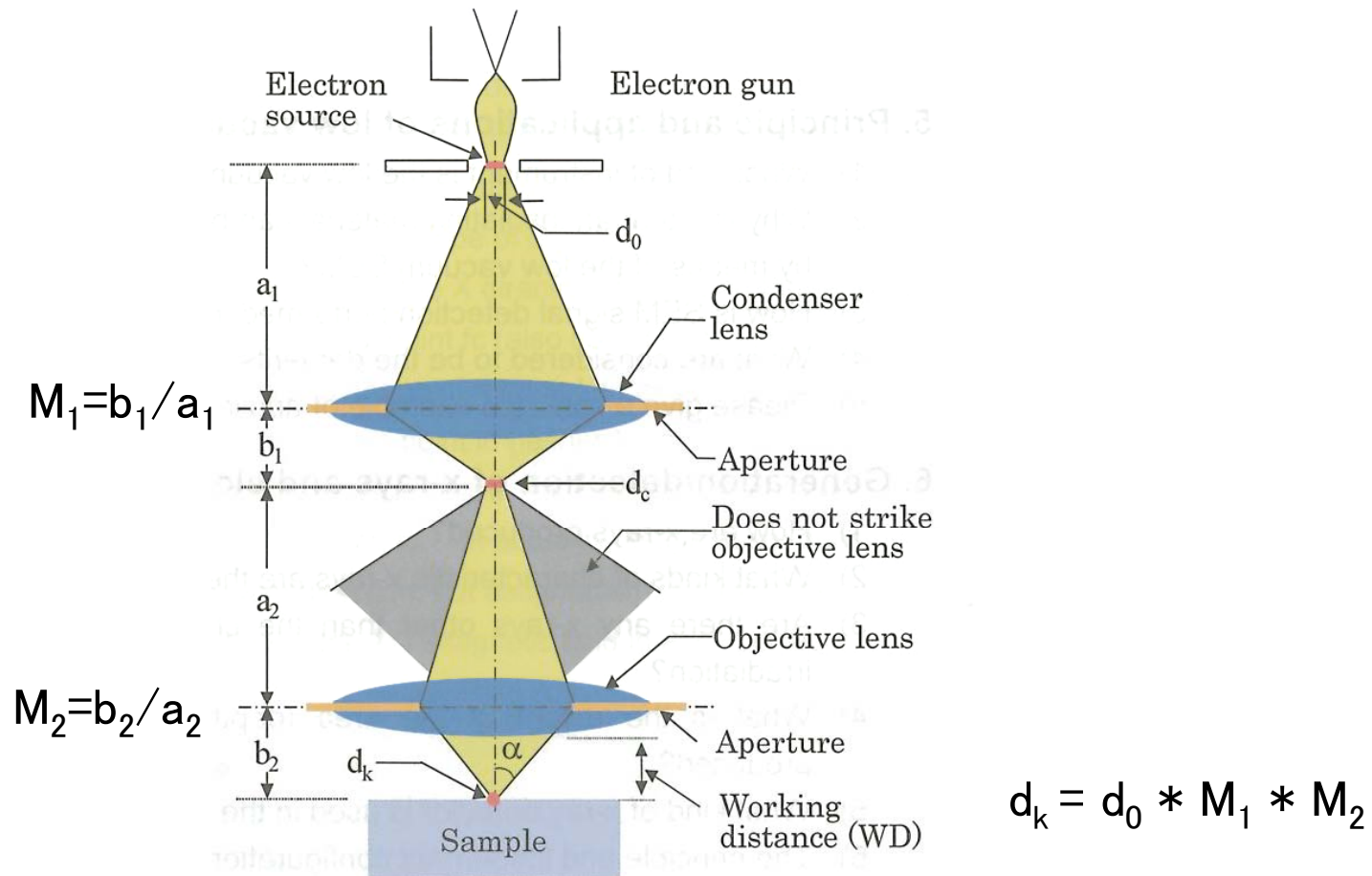
Coated paper for colour printer

Electron beam formation



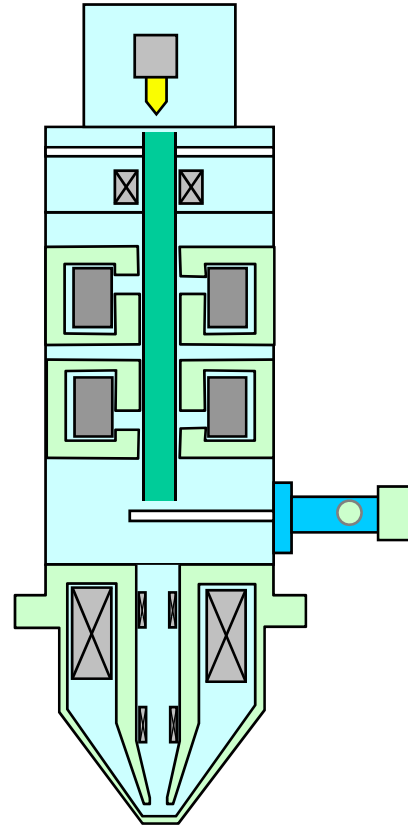
$$d_k = d_0 * M_1 * M_2$$

Electron beam formation



How can we obtain an even finer electron beam ?

Electron Optics



Tungsten (W) thermionic filament.

- pre-centered, self adjusting (ABS).

Auto Beam Setting (ABS).

- automatic optimization of filament saturation and beam axis.

Apertures integrated in removable Liner Tube (HITACHI patent)

- all fixed apertures can be accessed by the user for easy exchange

Quad Bias

- strong emission current also at low accelerating voltages

Objective aperture alignment

- electronical optimization of beam (AAA).

Objective lens.

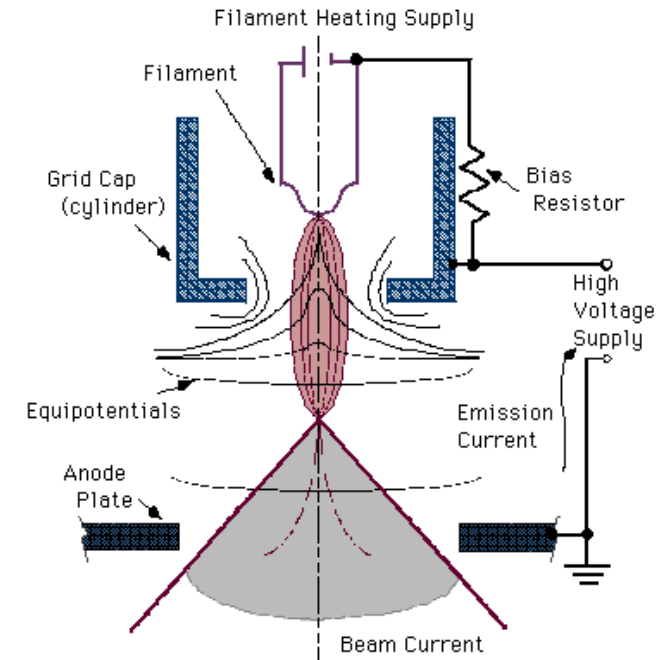
- optimized for high resolution even at low beam energies.
- large field-of-view, also unlimited in VP.

Source Comparison



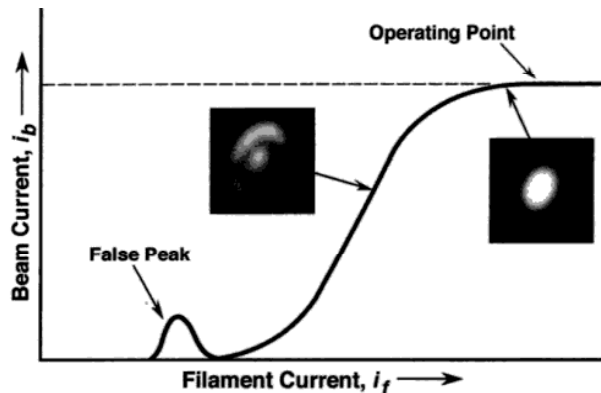
	W	LaB6	Schottky FE	Cold FE
Beam diameter	1 – 2 μm	1 – 2 μm	10 – 25 nm	3 - 5 nm
Temperature	2300° C	1500° C	1500° C	Room temp
Brightness	1	10	500	1000
Energy spread, ΔE	2.0 eV	1.5 eV	0.5 eV	0.2 eV
Stability, %/h	0.1 %	0.2 %	0.2 %	5 %
Probecurrent	50 nA -1 μA	50 nA -1 μA	>100 nA	20 nA
Life time	1 month	6 months	18 months	5 years
Gun vacuum	10^{-5} Torr	10^{-7} Torr	10^{-9} Torr	10^{-11} Torr

Electron Source: Tungsten Filament

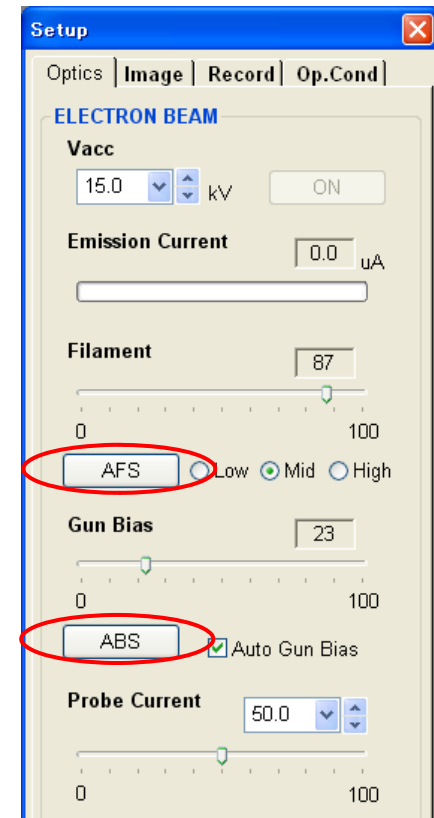


Tungsten filaments, operating life about 100 hours.

Cathods are delivered pre-centered, no fine-mechanical adjustment work required

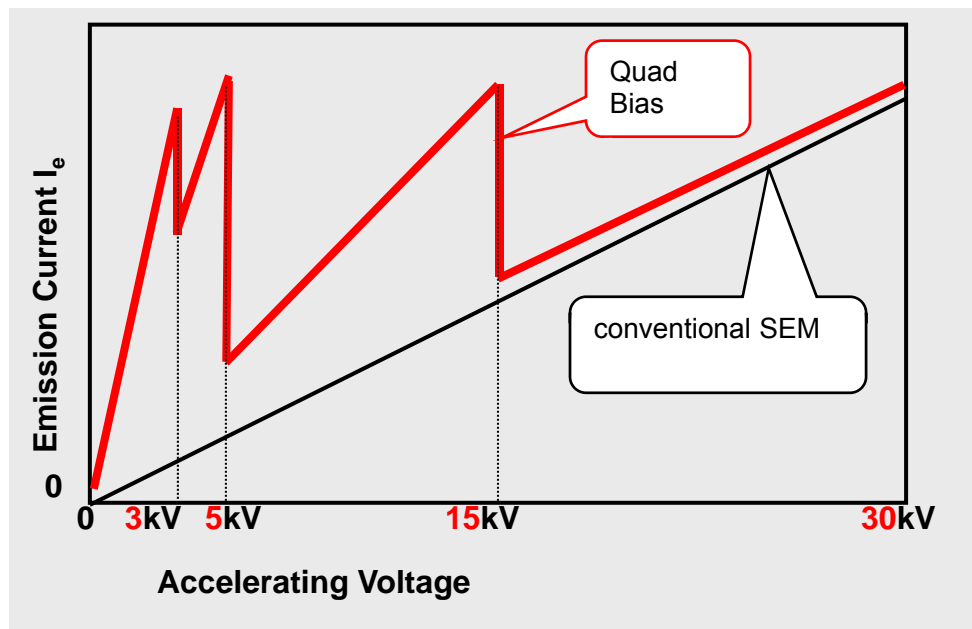


Re-adjustment of optics after filament exchange (filament saturation, beam axis) is automated - a simple mouse-click is enough. (ABS-function)



Quad-Bias: More Probe Current - also at low Beam Energies

Quad Bias circuitry allows high probe currents even at low accelerating voltages.

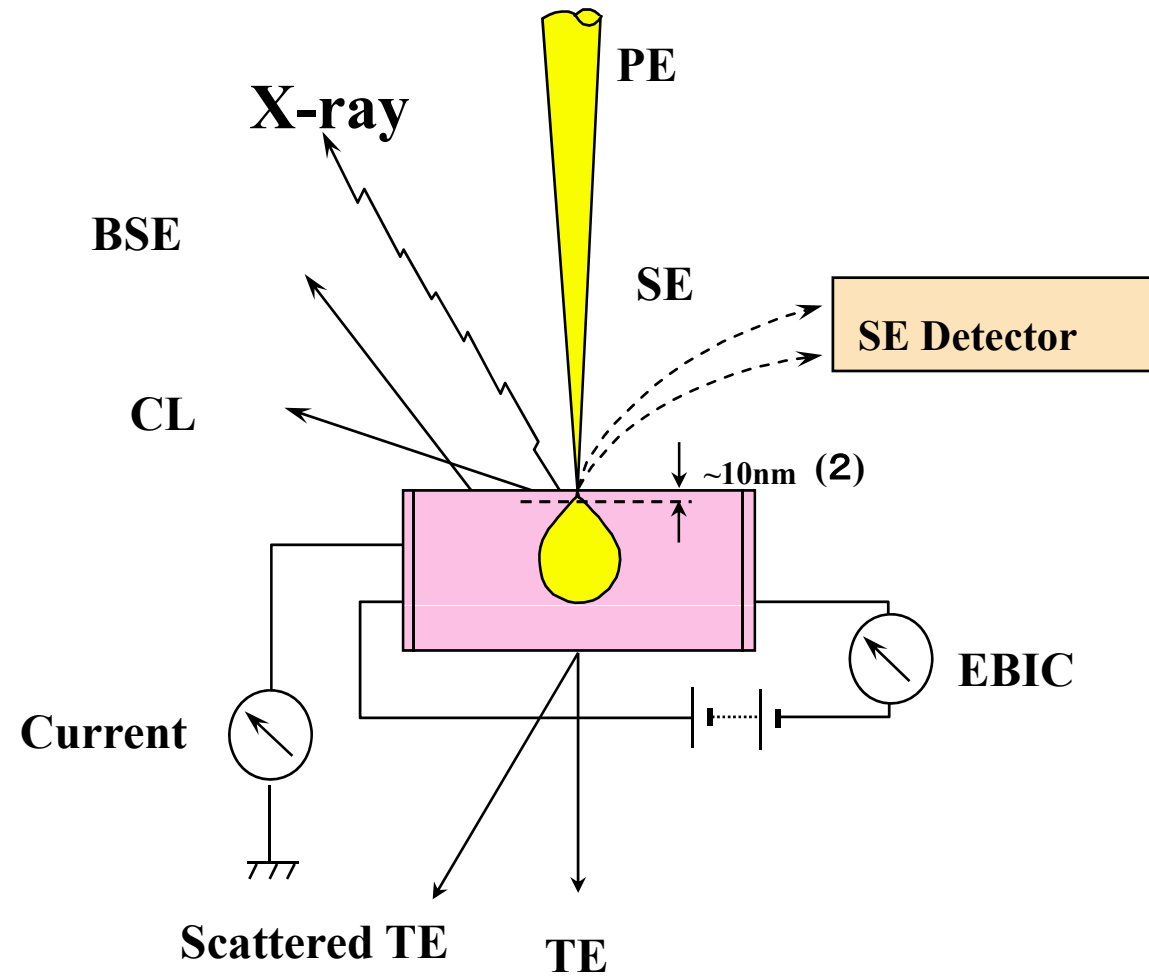


Advantages:

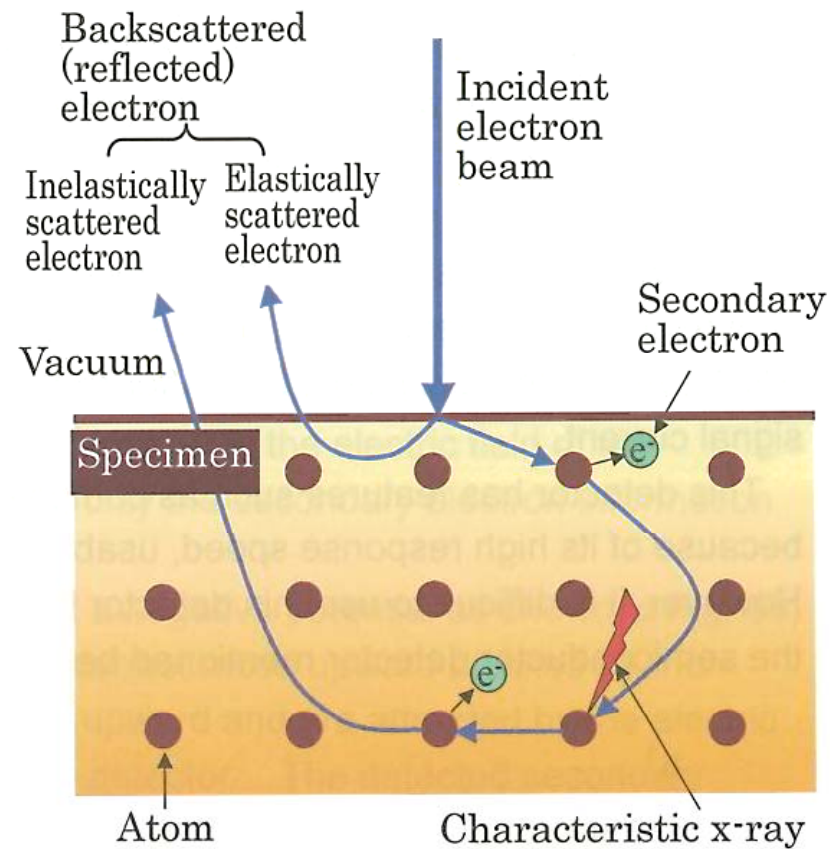
Superior imaging quality
(signal-to-noise ratio, image contrast)
for routine work at low beam energies

EDX analysis of thin layers at
low beam energies is enabled.

Signals in the SEM

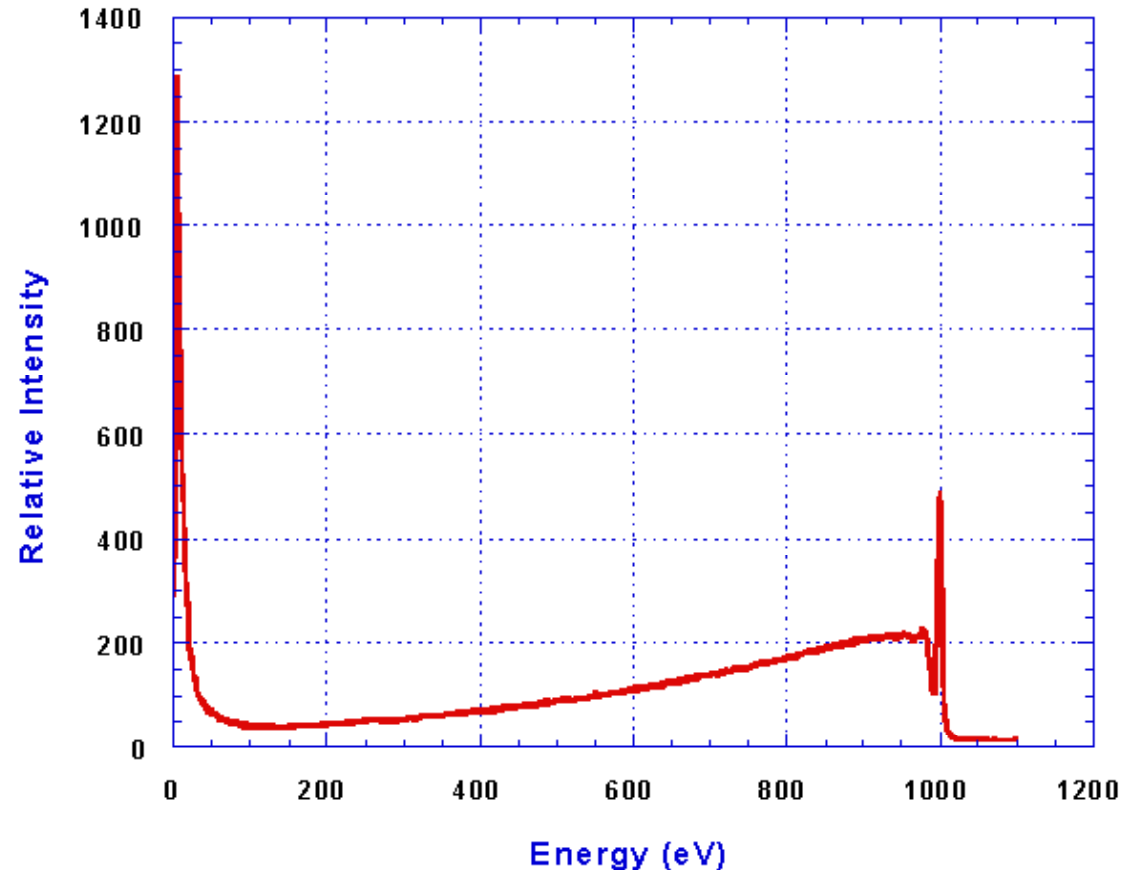


Emitted electrons



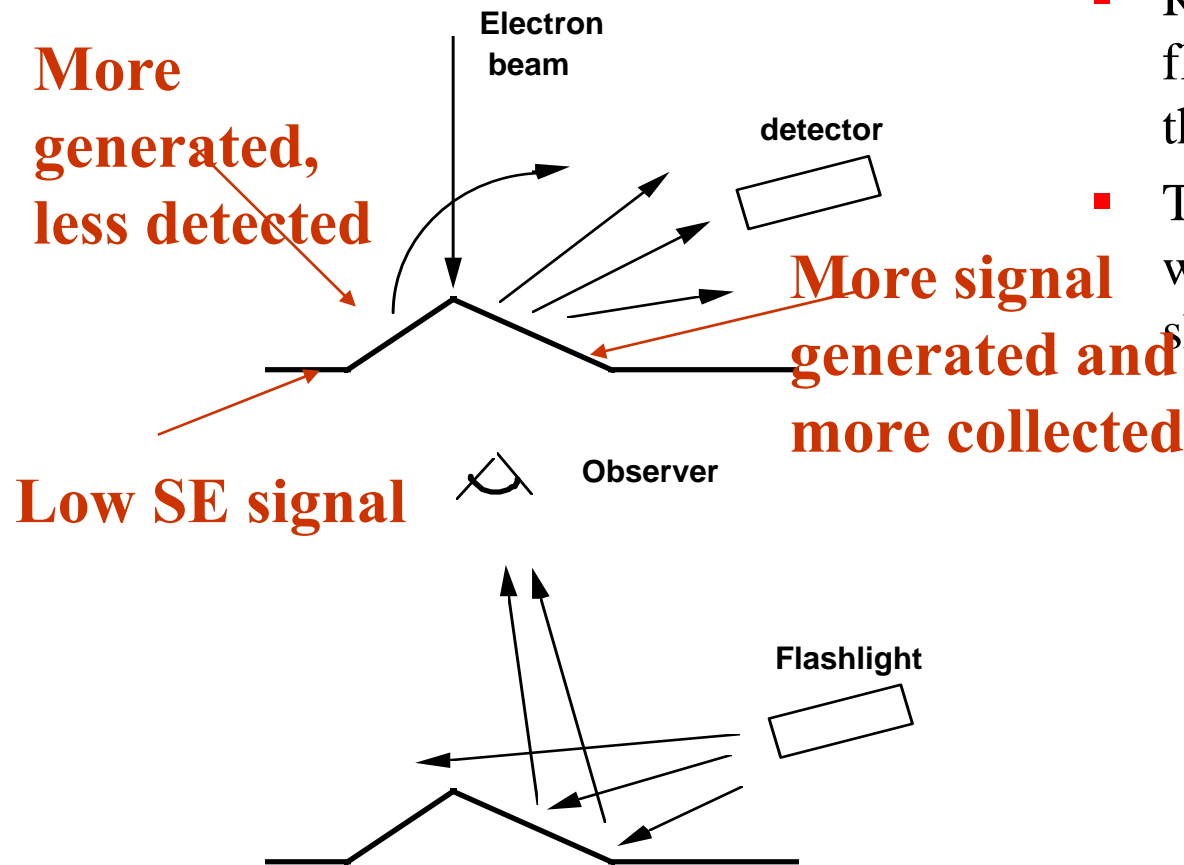
Emitted electrons

- When a sample is hit by an electron beam a variety of types of electron emission are available
 - Secondary electrons (energies 0 - 50eV)
 - Backscattered electrons (50eV to beam energy)
 - Elastically scattered electrons (i.e. those at the beam energy)



**Energy spectrum from an InP wafer at
1.0keV incident beam energy**

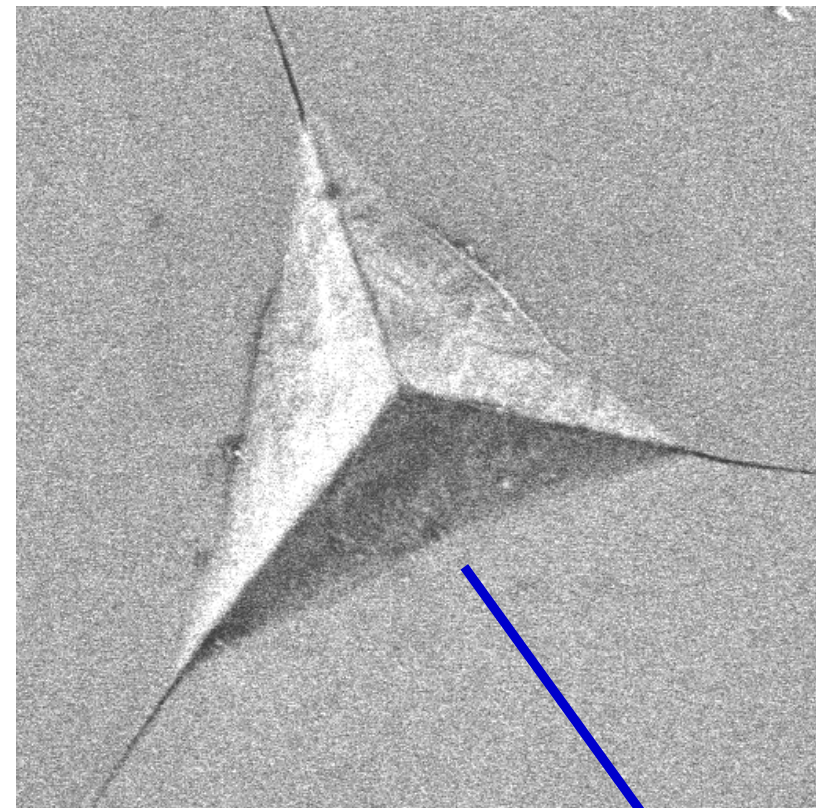
SE Contrast mechanisms



- Replace the detector by a flashlight, and imagine looking at the sample from the gun
- The SE image 'looks' like a real world image, light and dark, shadow and highlight
- A detector on the sample horizon will give strong shadows
- A detector above the sample gives no shadow information

SE Contrast mechanisms

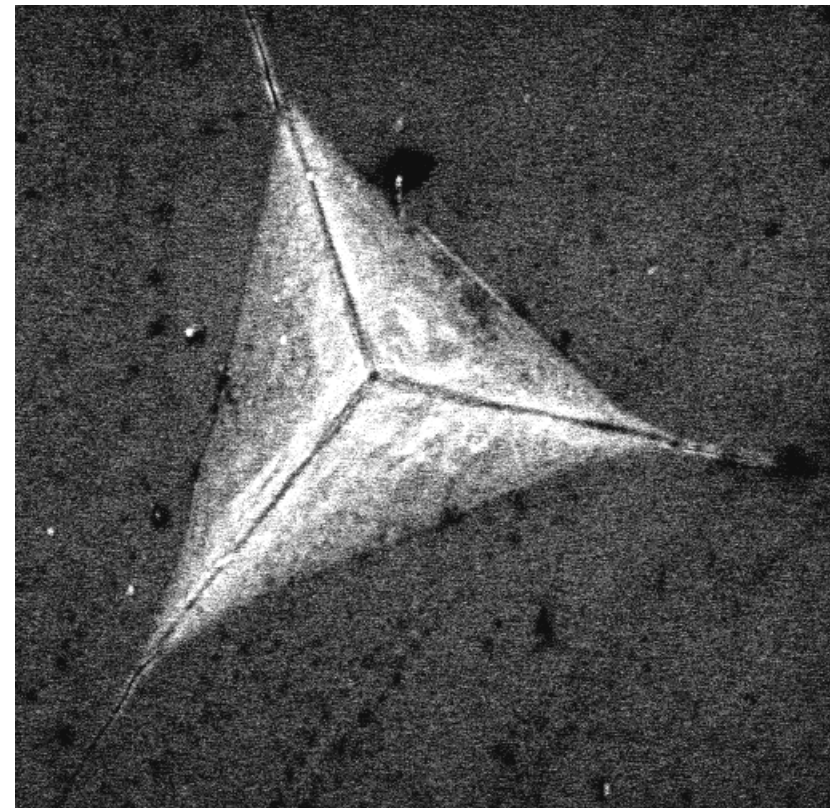
- The detector position therefore affects the image appearance
- The lower (ET) detector views the sample from one side and so the face looking away from the detector is shadowed
- Is this a pit or is it a pyramid?



To detector

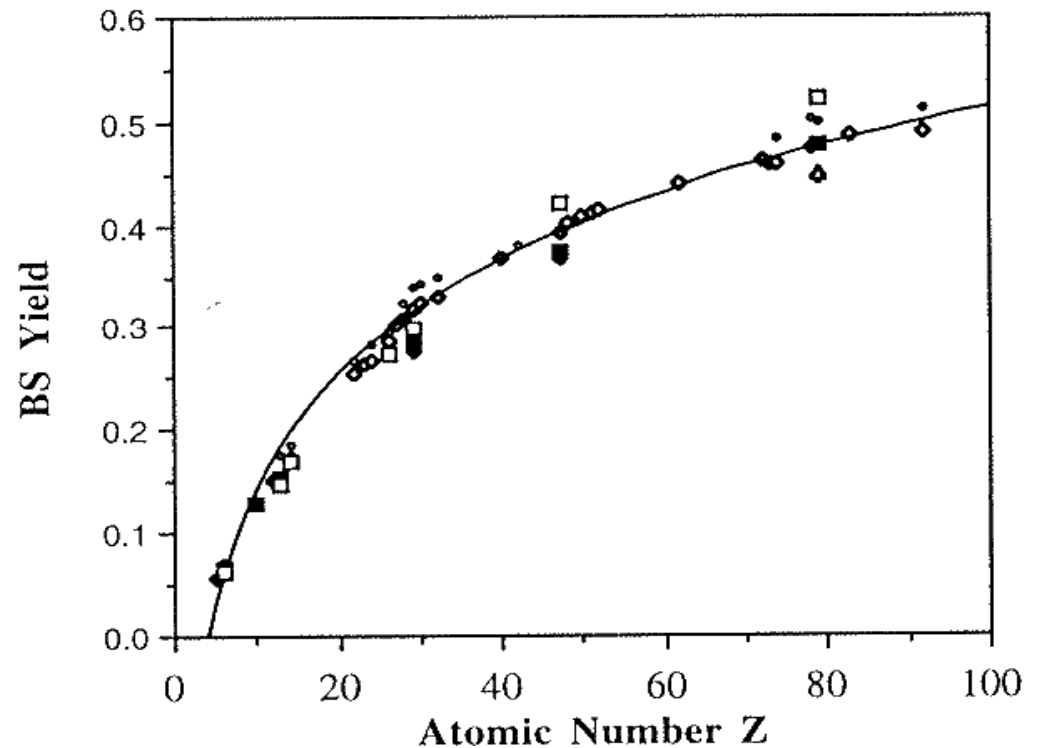
SE Contrast mechanisms

- The upper (in-lens) detector views the sample from above
- The SE collection is now symmetrical and so all faces of the indent are equally visible.
- They are brighter than the flat surface because of topographic contrast.



Backscattered electrons

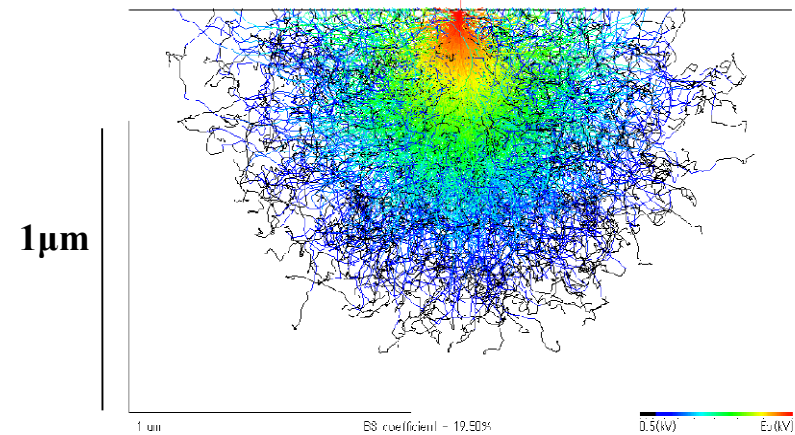
- The Backscattered Electron yield is
 $\eta = N(\text{BS}) / N(\text{incident})$
- η increases with Z and incident angle
- η does not depend much on energy



Experimental BS yields

Interaction volume

- Images are formed because of beam interaction with the sample
- This happens in a volume, not in a point
- The size of this volume varies with beam energy...

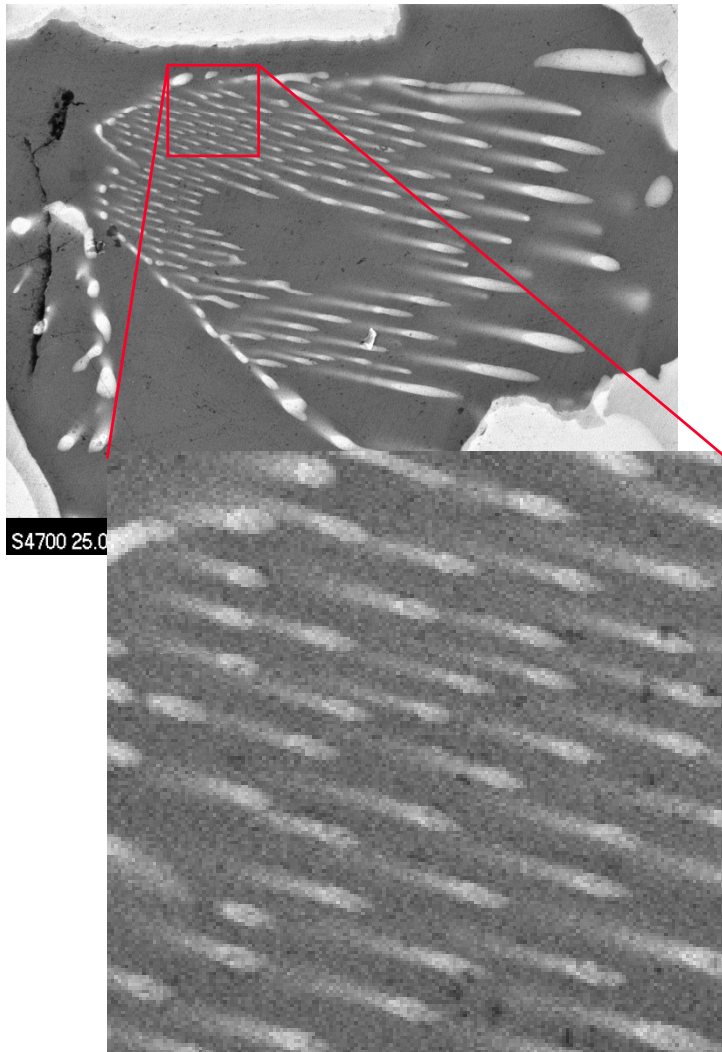


Vacc : 10kV

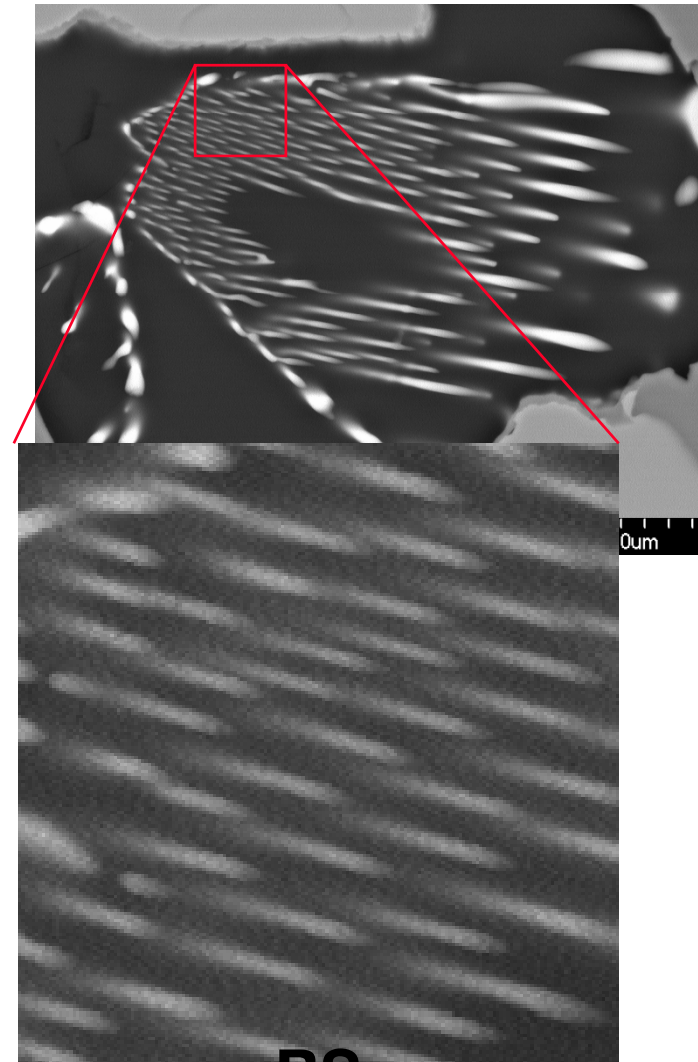


Vacc : 1kV

SE & BSE at 25 kV

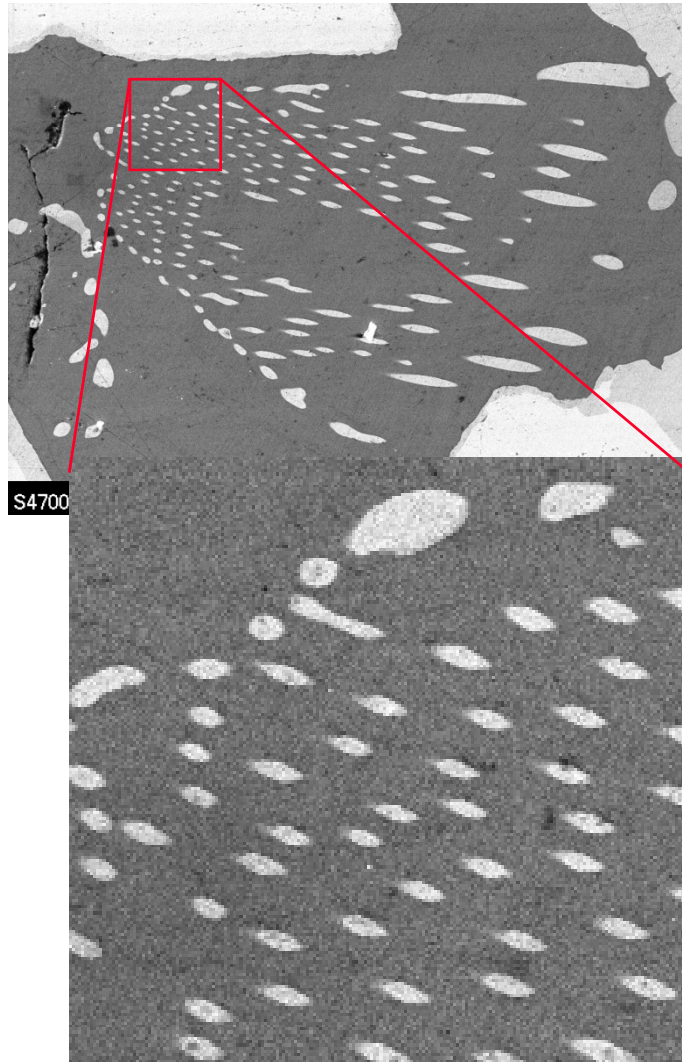


SE

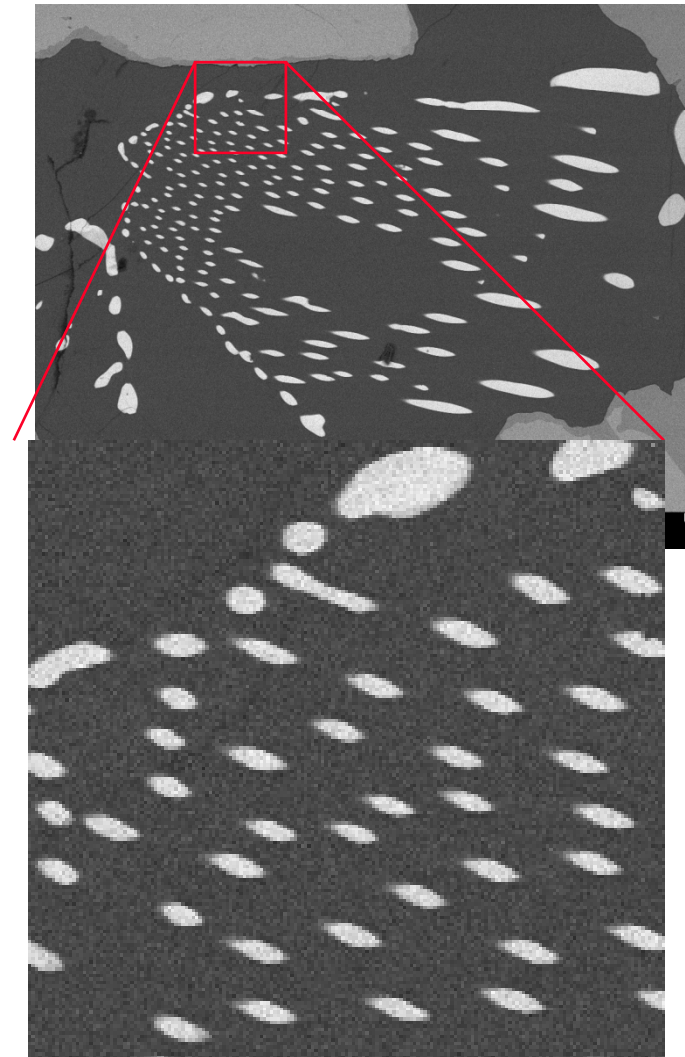


**BS
E**

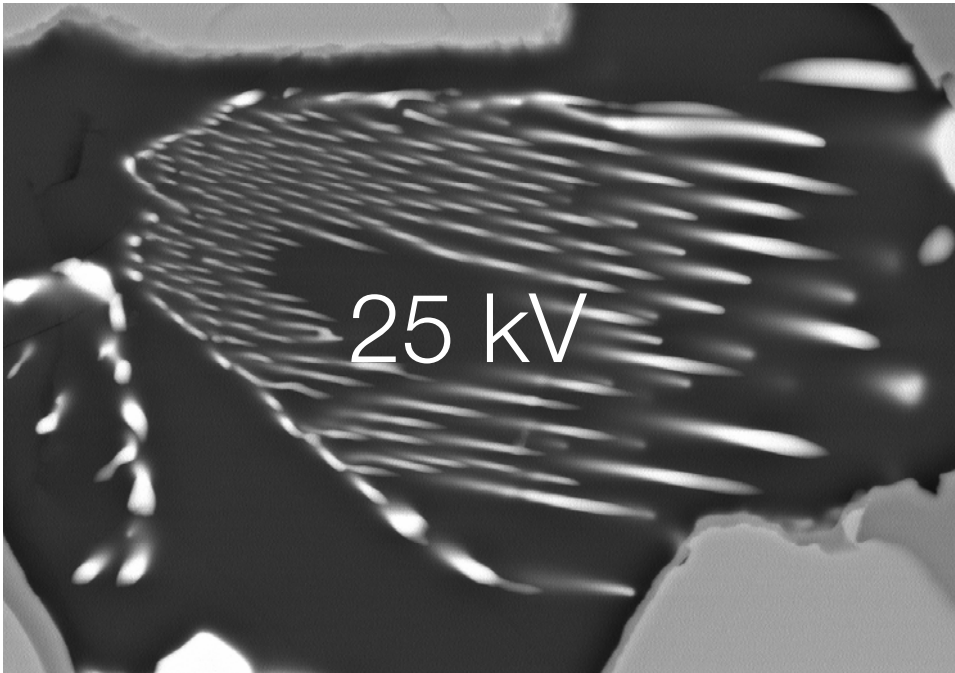
SE & BSE at 5 kV



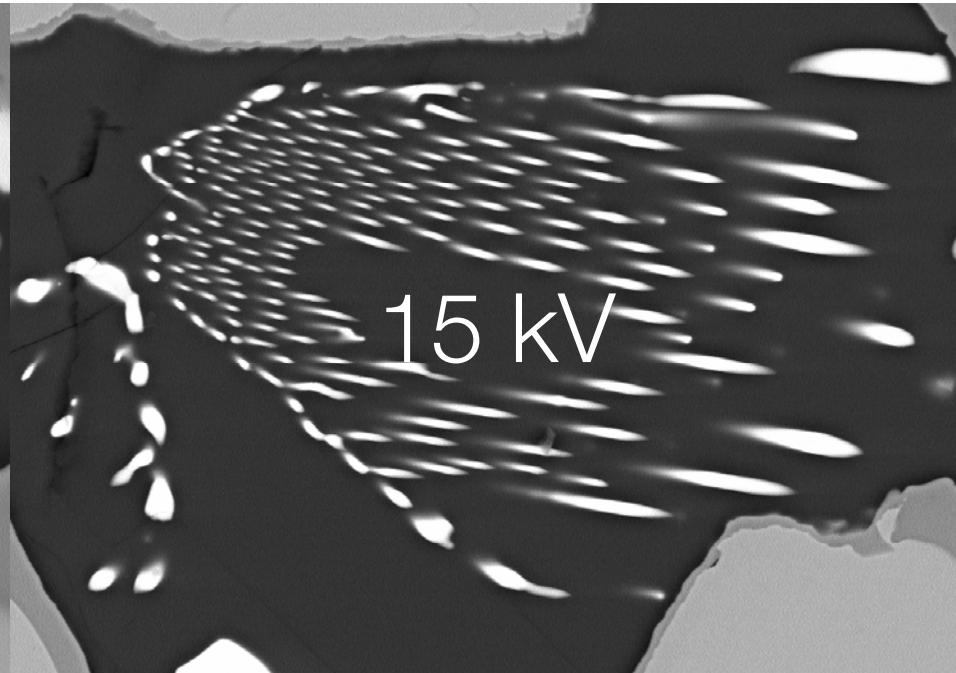
SE



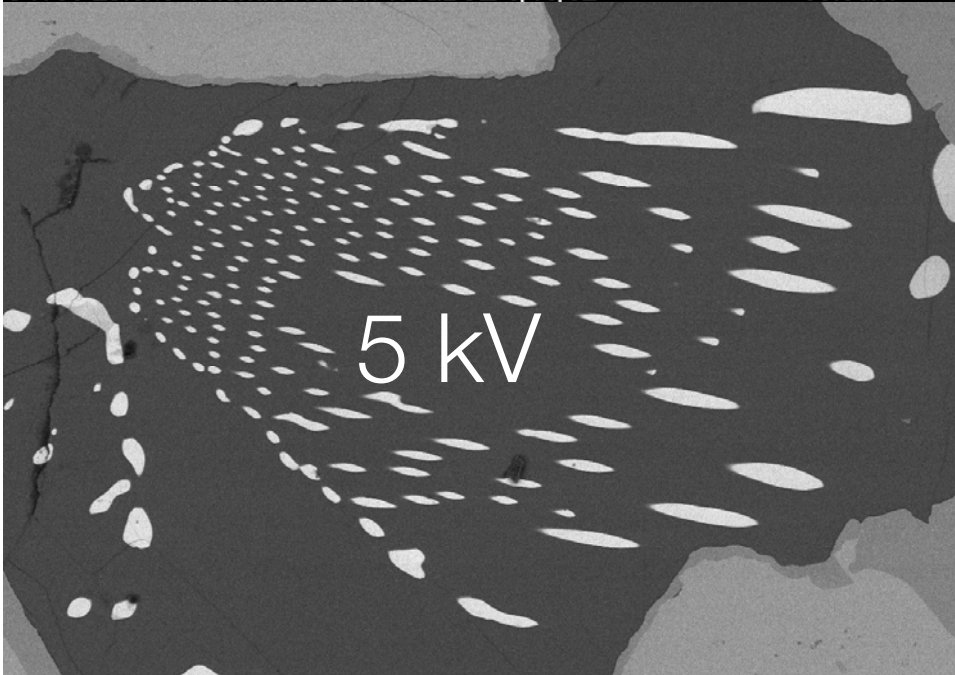
**BS
E**



S4700 25.0kV 11.5mm x1.50k YAGBSE 6/18/02 30.0um



S4700 15.0kV 11.7mm x1.50k YAGBSE 6/18/02 30.0um

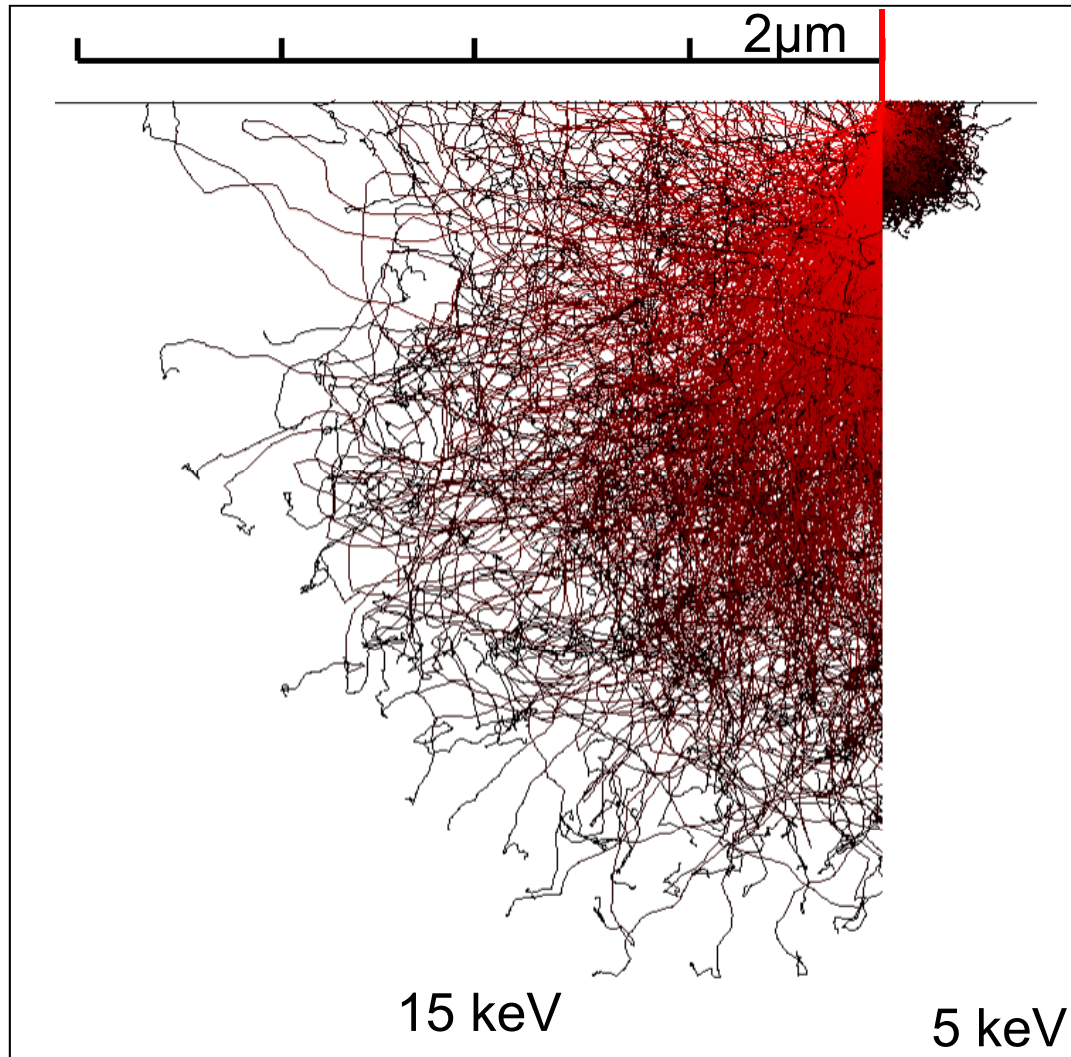


S4700 5.0kV 11.7mm x1.50k YAGBSE 6/18/02 30.0um

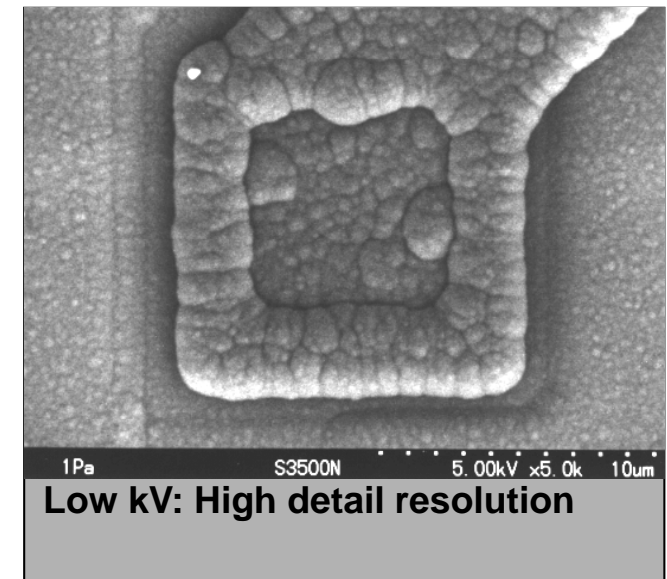
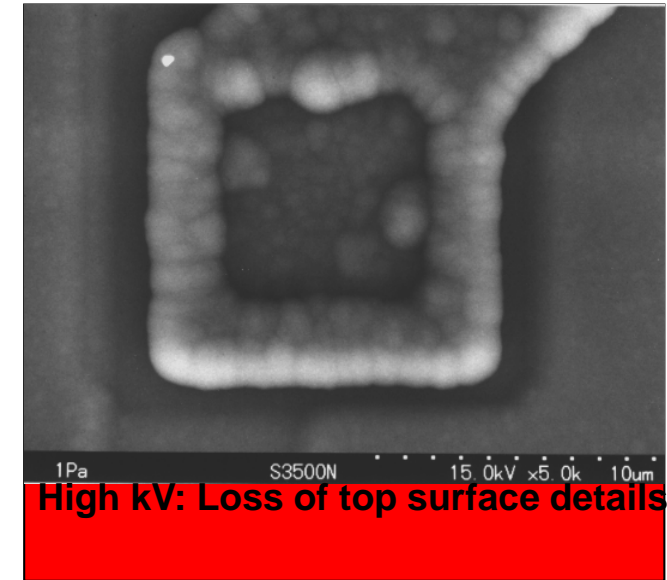


S4700 1.0kV 4.6mm x1.50k SE(U,-150) 6/18/02 30.0um

Why to use Low Beam Energies?



Sample: Aluminium



BSE Detectors

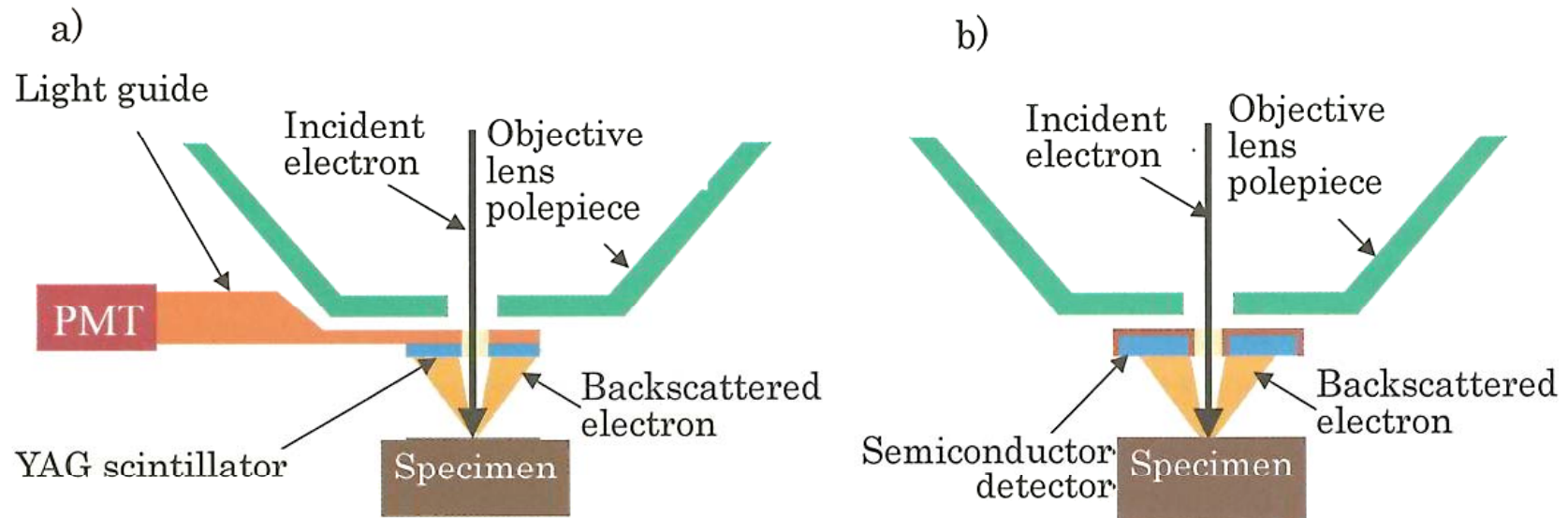
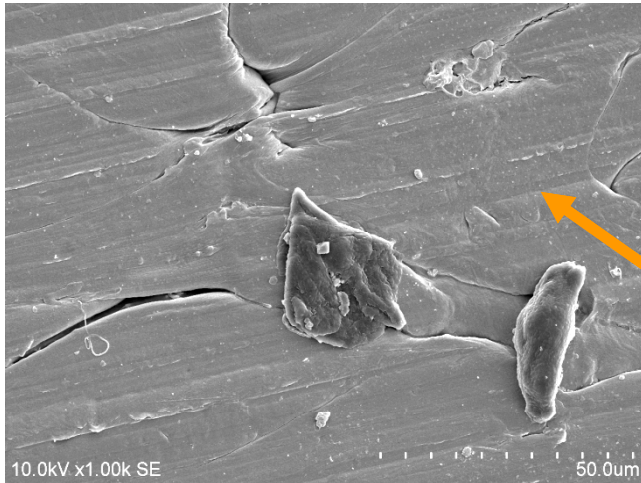


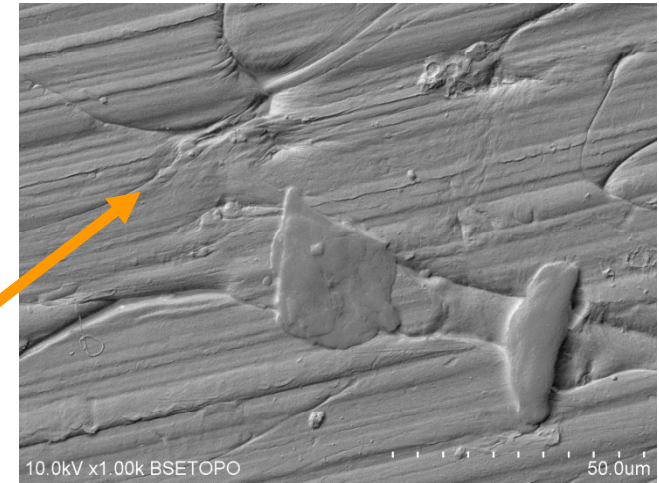
Fig. 6 Composition of YAG Detector a) and Semiconductor Detector b)

Available image signals

SE



BSE TOPO



DETECTOR

SE BSE X-Ray

ABC Link

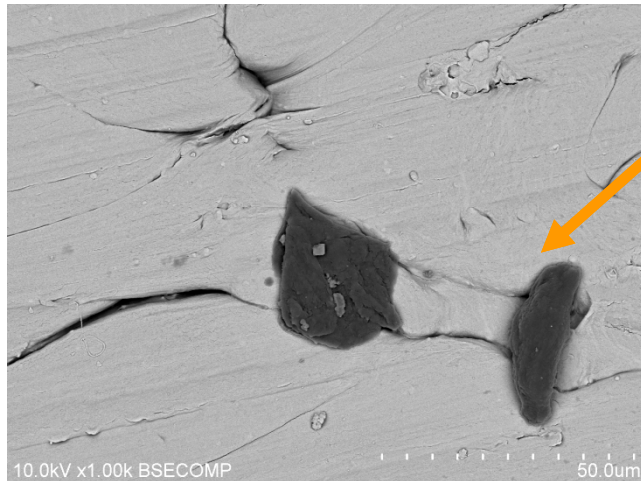
COMP TOPO 3D

BSE Gain

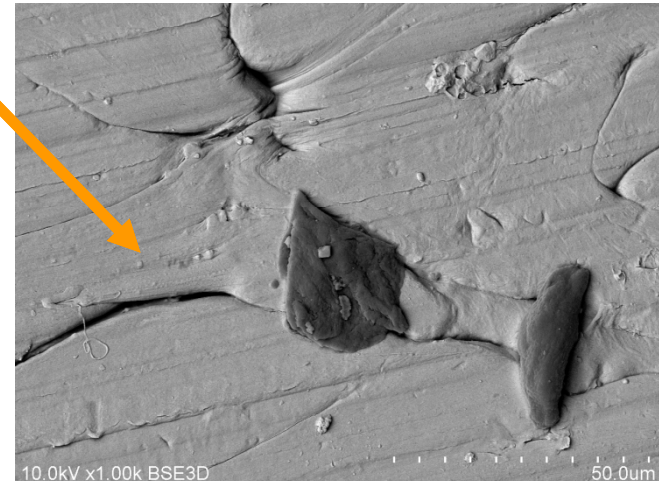
1 4

Analysis ← Std. → H.R.

Detail...



BSE COMPO

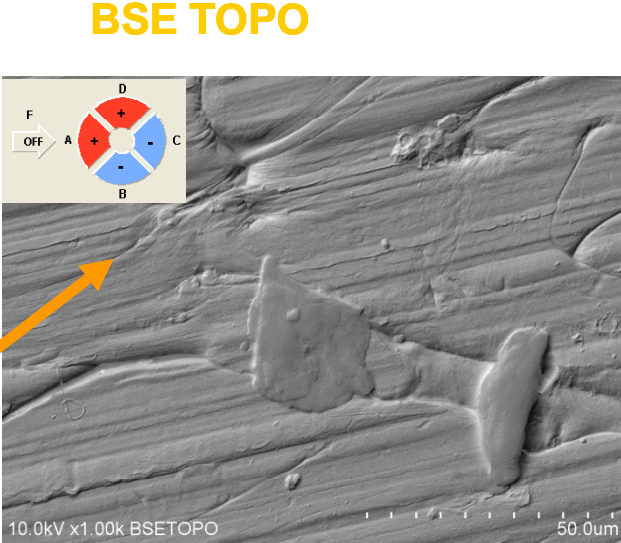


BSE 3D

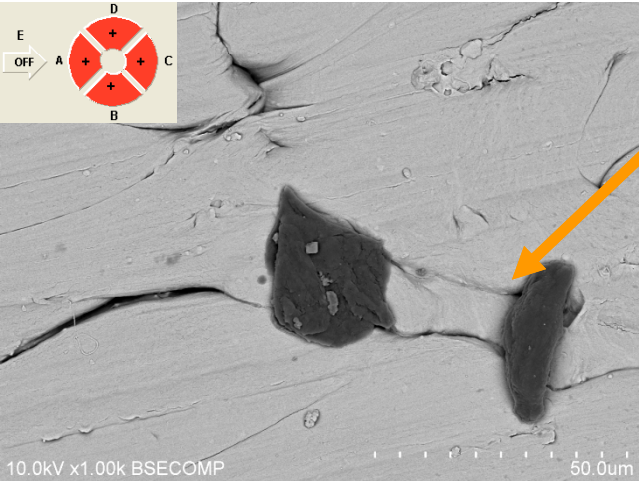
Material Contrast and More: High Sensitivity 4+1 BSE Detector



SE
(Everhart Thornley)



BSE TOPO



BSE COMPO

DETECTOR

SE BSE X-Ray

ABCD Link

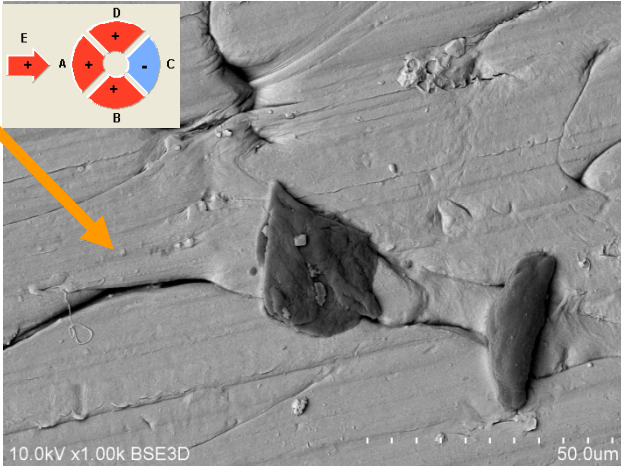
COMP TOPO 3D

BSE Gain

1 4

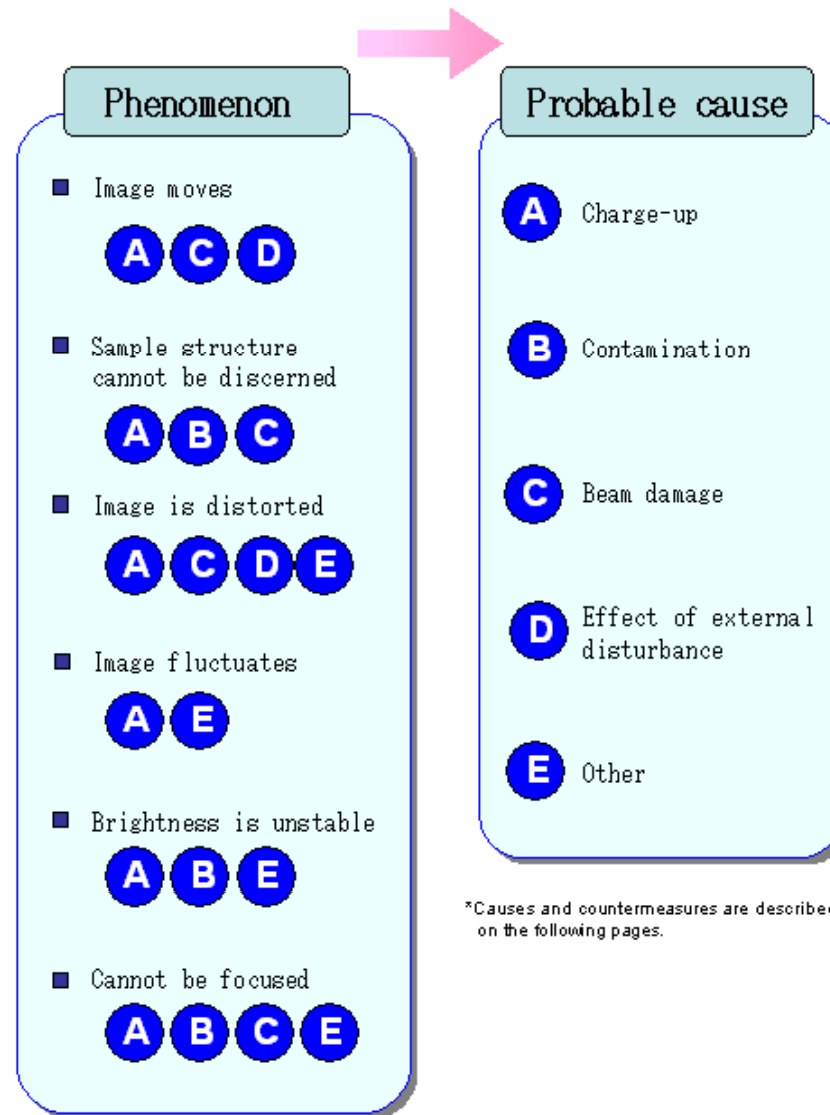
Analysis ← Std. → H.R.

Detail...

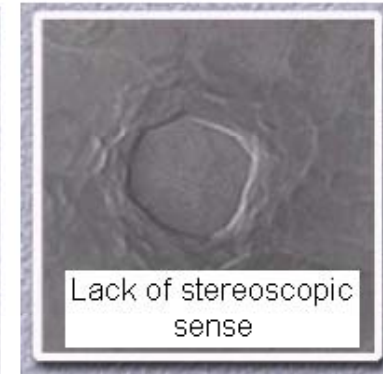
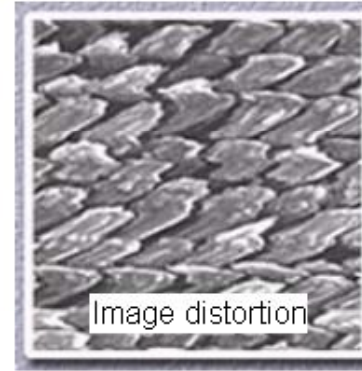
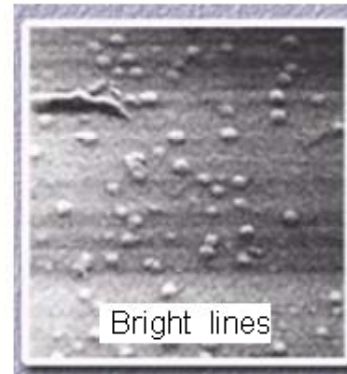


BSE 3D

Imaging problems



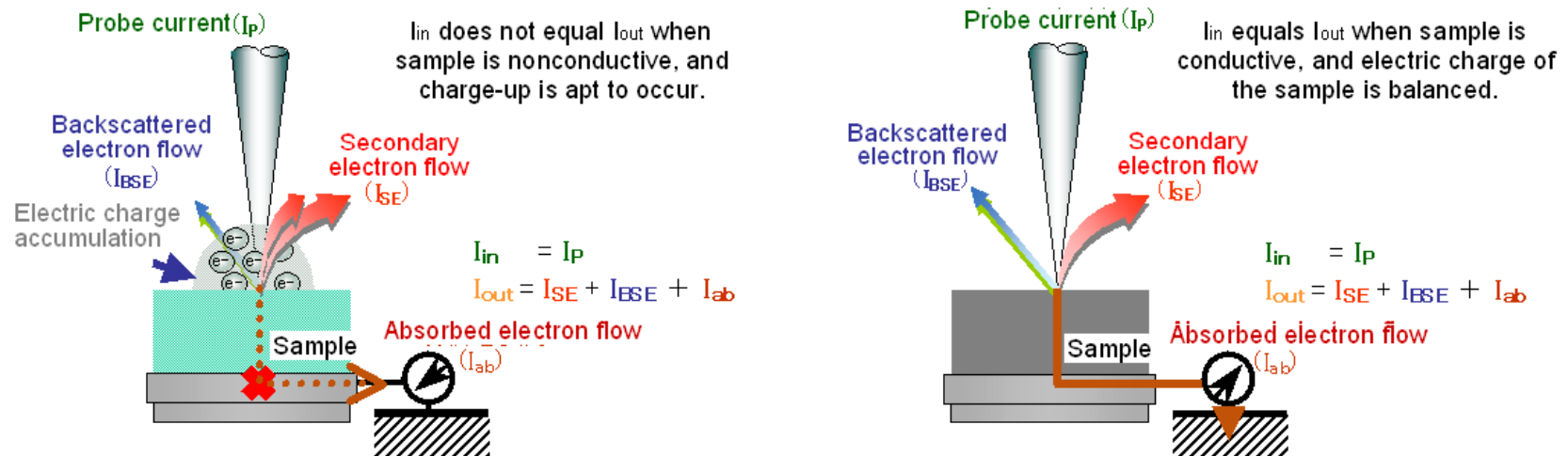
Charge up



Examples of Charge-up Phenomenon

Charge-up occurs during observation of non-conductive samples, and may be conspicuous especially when scan speed or magnification is changed.

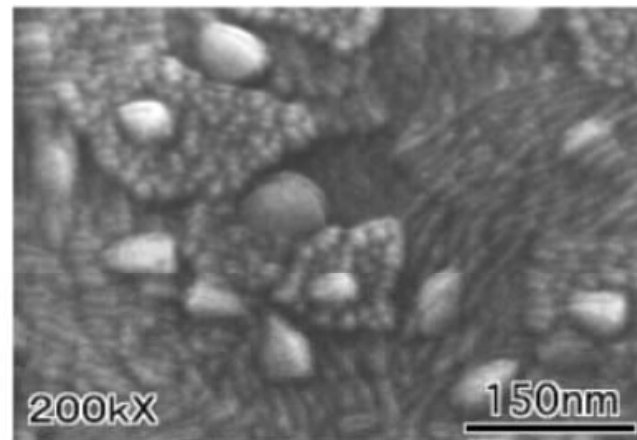
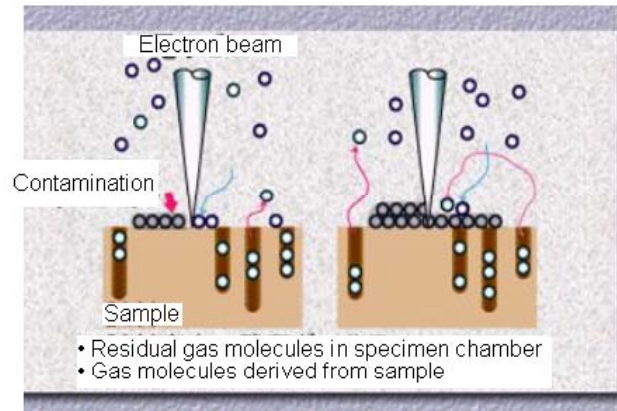
Charge up



Countermeasures for the charge-up phenomenon.

1. Reduce the accelerating voltage.
2. Reduce the sample irradiating current.
3. Apply a metal coating.
4. Integrate the image (form an image by superimposing images obtained at rapid scan)
5. Observe images in low vacuum mode
6. Utilize a low-acceleration BSE signal (eliminate SE signal by means of signal varying mechanism)

Contamination



Magnification
reduced



Example of Sample Contamination
Hitachi High-Technologies Europe GmbH

Contamination



Countermeasures against contamination

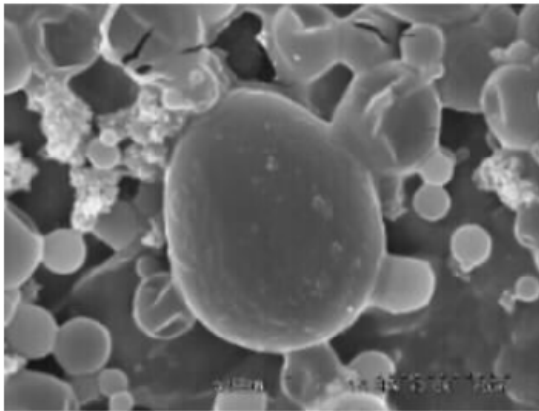
The following steps are required in order to reduce the contamination:

- Reduction of residual gas molecules in specimen chamber (improvement of vacuum level)
- Reduction of gas molecules derived from sample

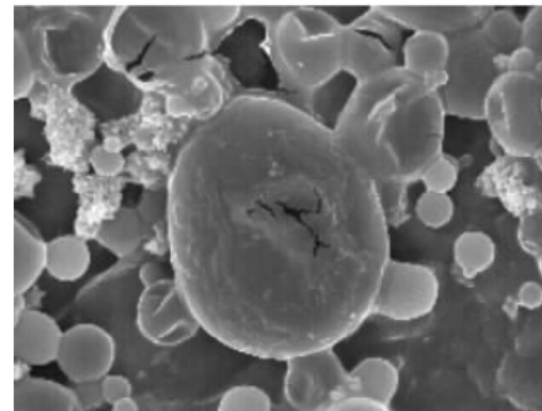
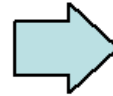
Concrete measures to achieve the above reductions are as follows.

1. Use a minimum amount of conductive paste or tape when mounting the sample in the instrument.
2. Thoroughly dry the conductive paste with a dryer or the like prior to inserting sample into the instrument for observation.
3. Heat and degas the sample in a vacuum device.
4. Carry out focusing as quickly as possible and avoid observing the same location for a long time especially at high magnification.
5. Observe samples while cooling the sample surroundings with a cold trap.

Beam damage



No beam damage



Damage due to beam irradiation

Countermeasures against contamination

1. Reduce the sample irradiating current
2. Lower the accelerating voltage
3. Apply (metal) coating to the sample (to improve heat conductivity)
4. Observe the sample while cooling it

Outside disturbance



Countermeasures against vibration

1. Keep the instrument well away from vibration sources such as air-conditioner or pumps.
2. Do not let high-voltage cables from the column come in contact with the wall or other installation items
Lower the accelerating voltage
3. Don't let the draft from an air-conditioner outlet contact the column directly.

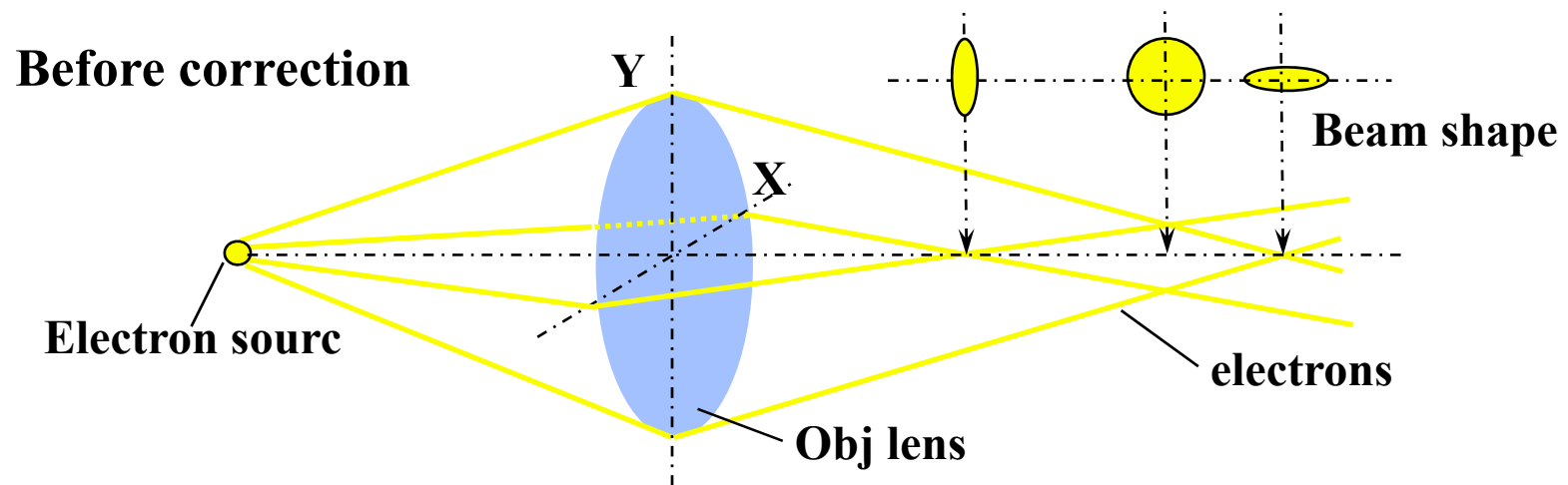
Countermeasures against magnetic field

1. Keep the instrument well away from magnetic field sources such as transformer or large capacity power cables
Reduce the sample irradiating current
2. Lower Shorten the working distance (see 1-7 or 4-5 in Chapter 6) and apply strong excitation to the condenser lens to counter the effect of a magnetic field.
3. Use a magnetic field cancelling system

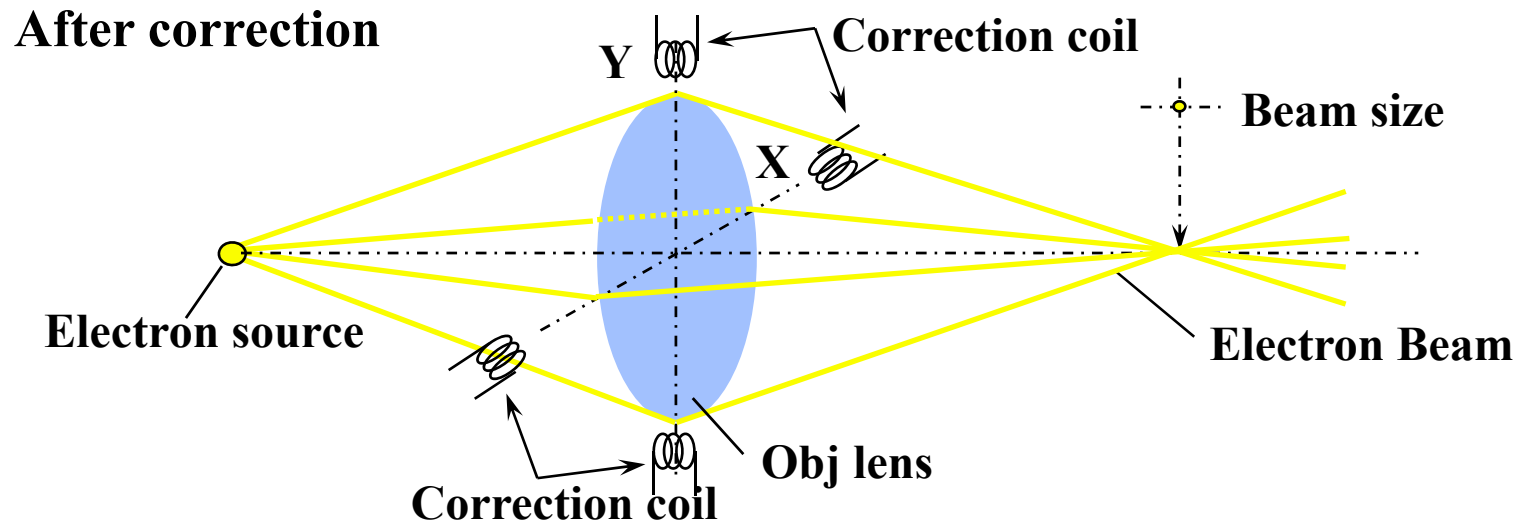
Other problems

Symptom	Possible causes
Sample moves	<ul style="list-style-type: none">• Sample is not fixed in place adequately when sampling.• Screw of specimen holder is not tightened adequately.• Sample is inserted incompletely onto specimen stage.• Compressor operated while the stage is locked.
Image fluctuates	<ul style="list-style-type: none">• Irradiating current is low (change the excitation of condenser lens).• Lower image is being observed at short WD in the case of semi in-lens SEM.• WD is long in low vacuum SEM observation mode.
Focus cannot be obtained	<ul style="list-style-type: none">• Inadequate optical axis alignment• Objective aperture contaminated• Recheck the instrument parameters.

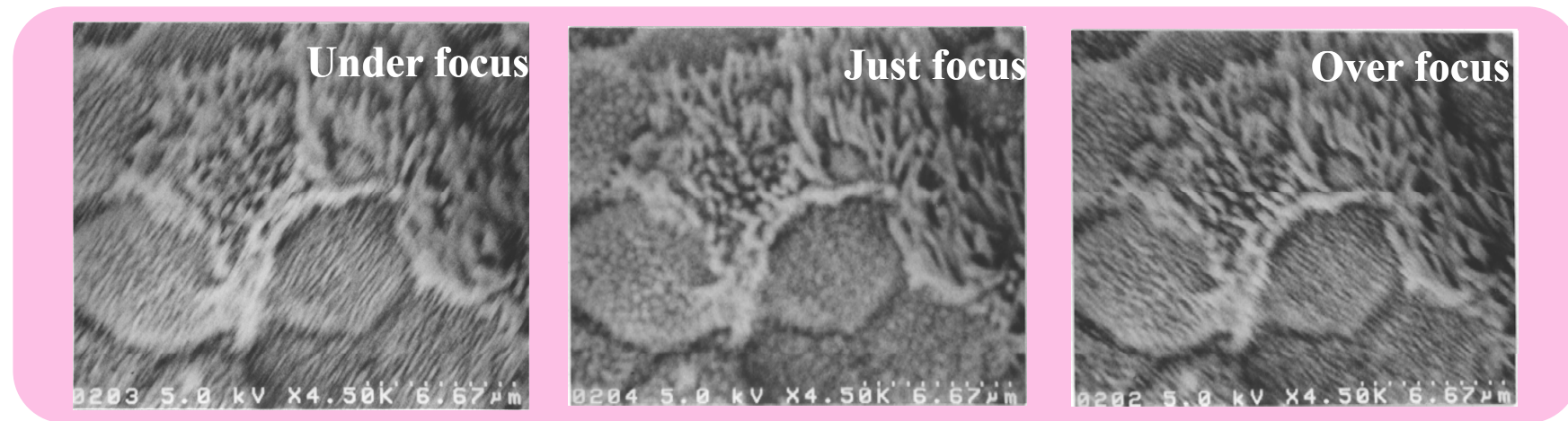
Astigmatism



Astigmatism



Astigmatism

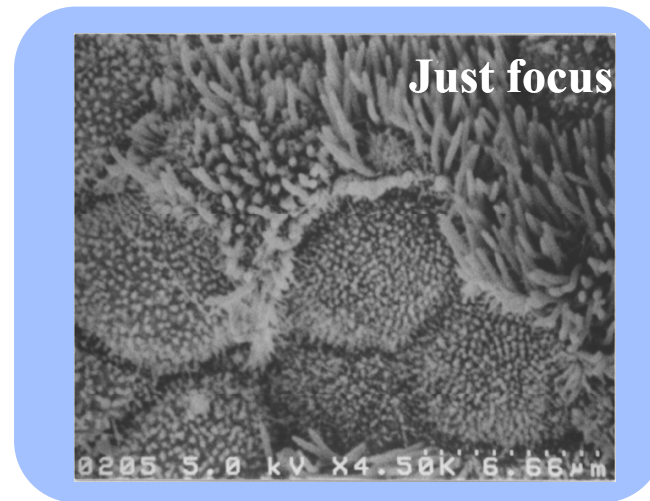


Before correction

Specimen: Trachea of rat

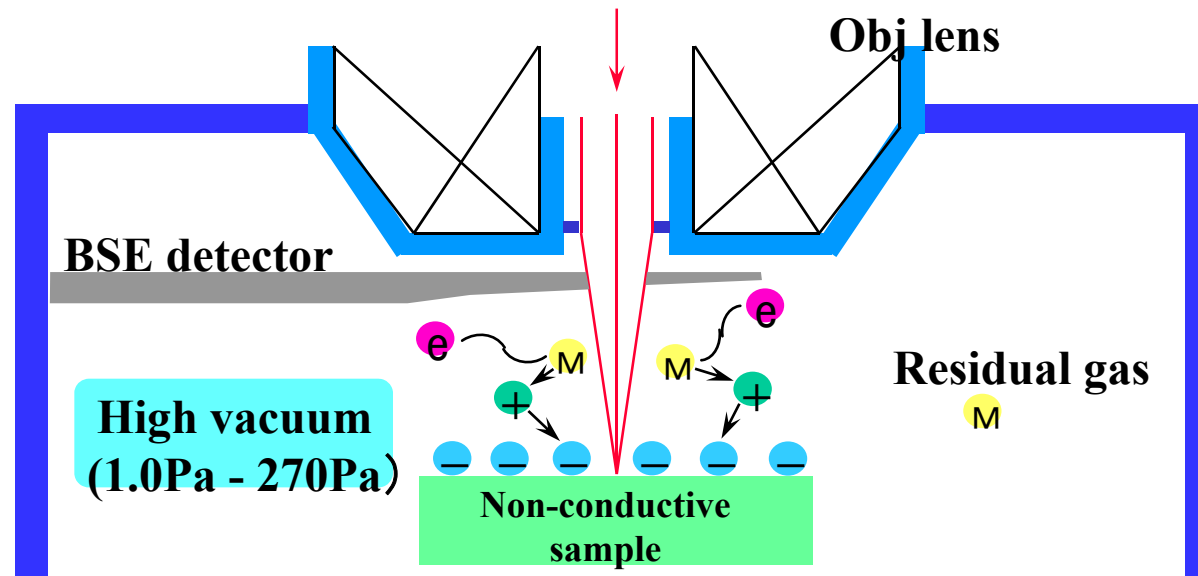
Astigmatism

After correction



Specimen: Trachea of rat

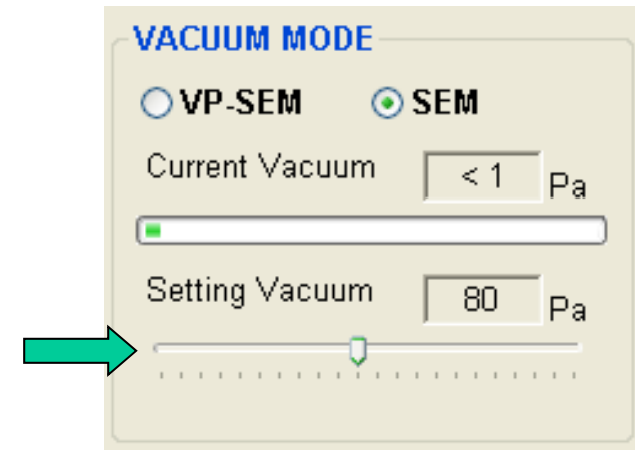
Variable Pressure



Pressure	Mean Free Path
10^{-3}Pa	40mm
13Pa	3mm
270Pa	0.1mm

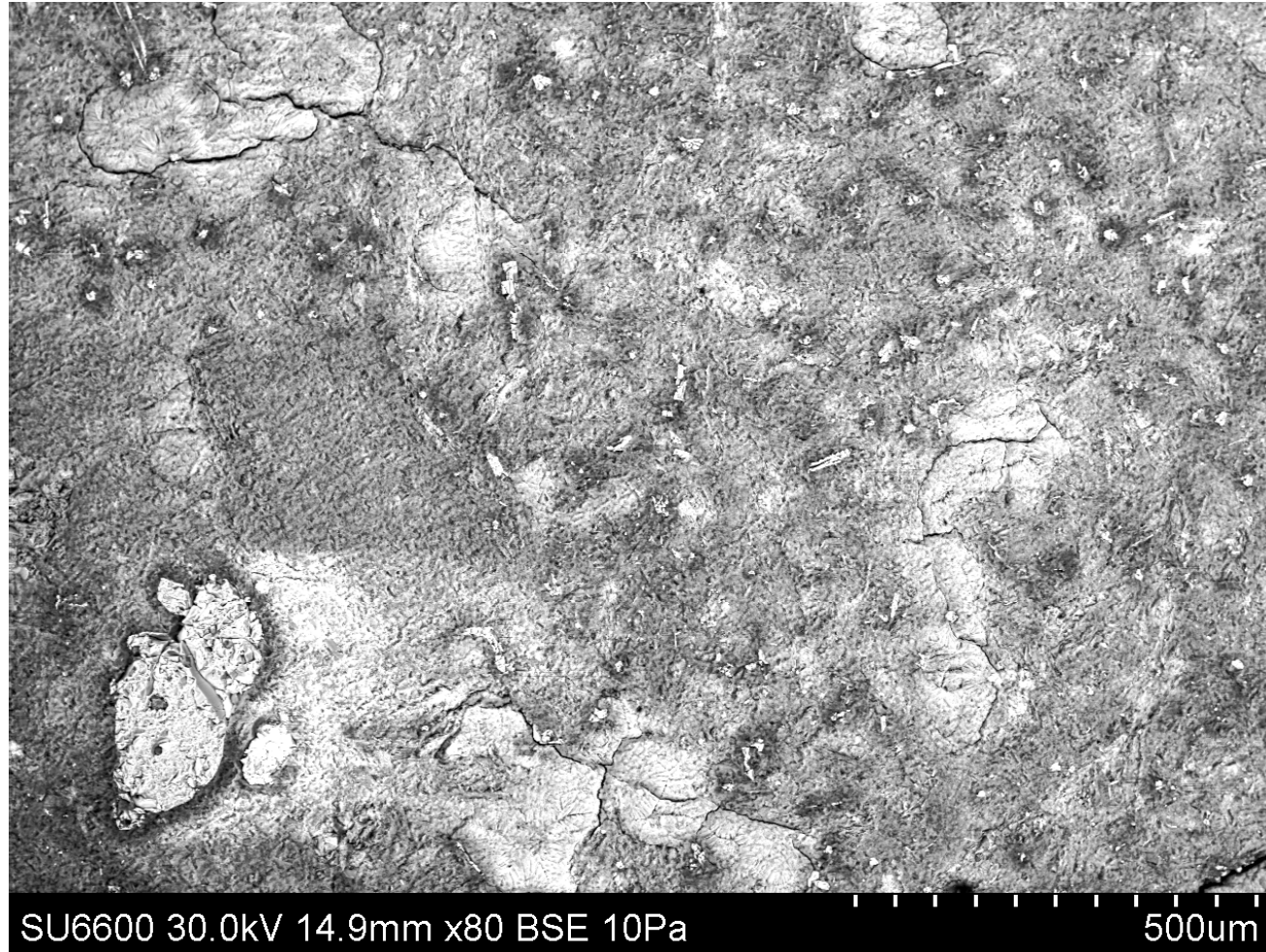
SEM with Variable Chamber Pressure

- Conductive samples: Observation in high-vacuum
- Non-conductive samples: Observation in low-vacuum
 - No sample coating required.
 - If charging occurs, simply the chamber pressure is gradually increased until the charging disappears.



- Investigation of humid or oily samples
 - An optional cool stage chills at ca. 60Pa chamber pressure the sample to -20°C , so that the evaporation of water is mostly suppressed
(balance point between solid and gaseous phase)

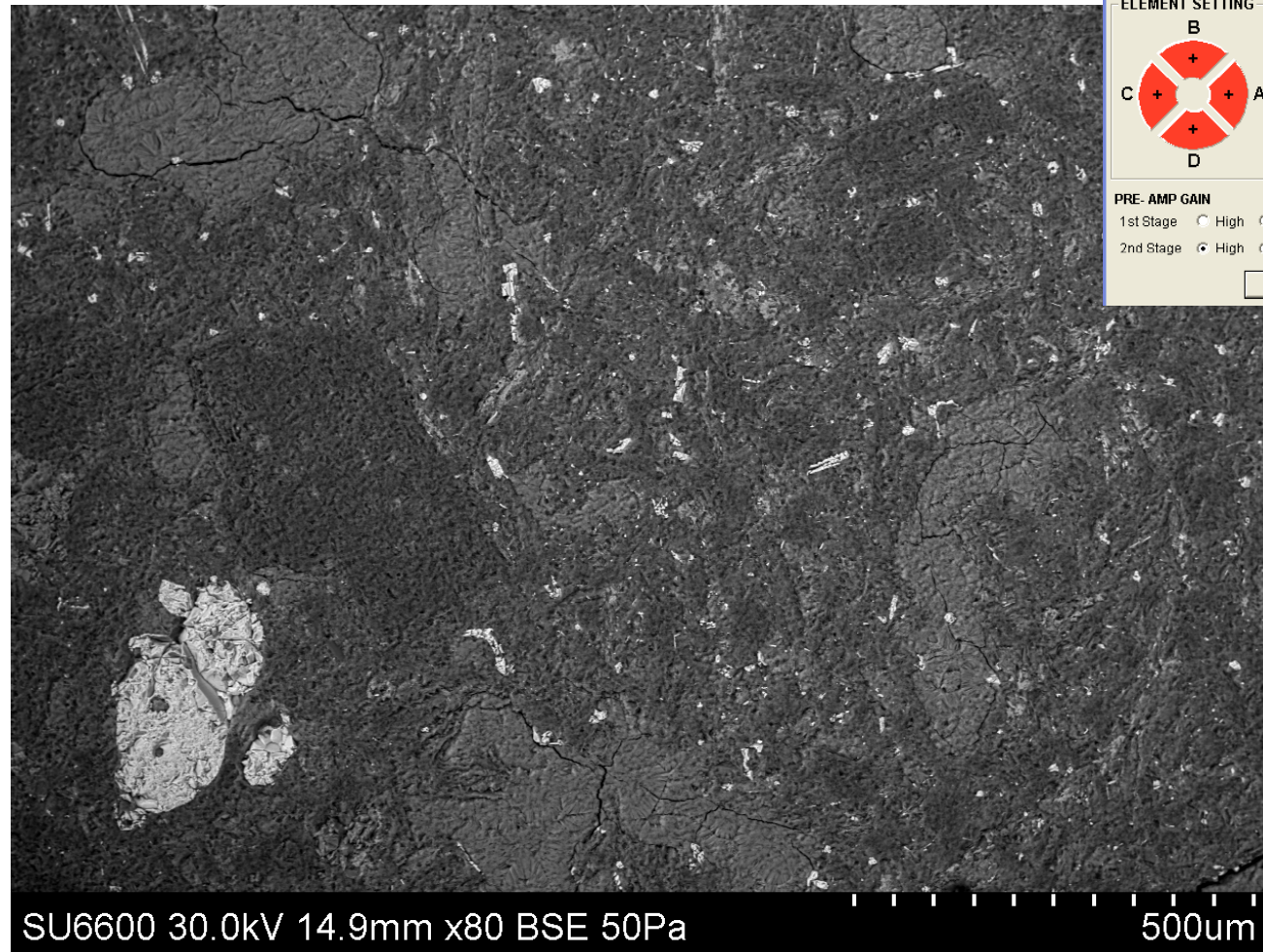
Variable Pressure



Basalt - uncoated

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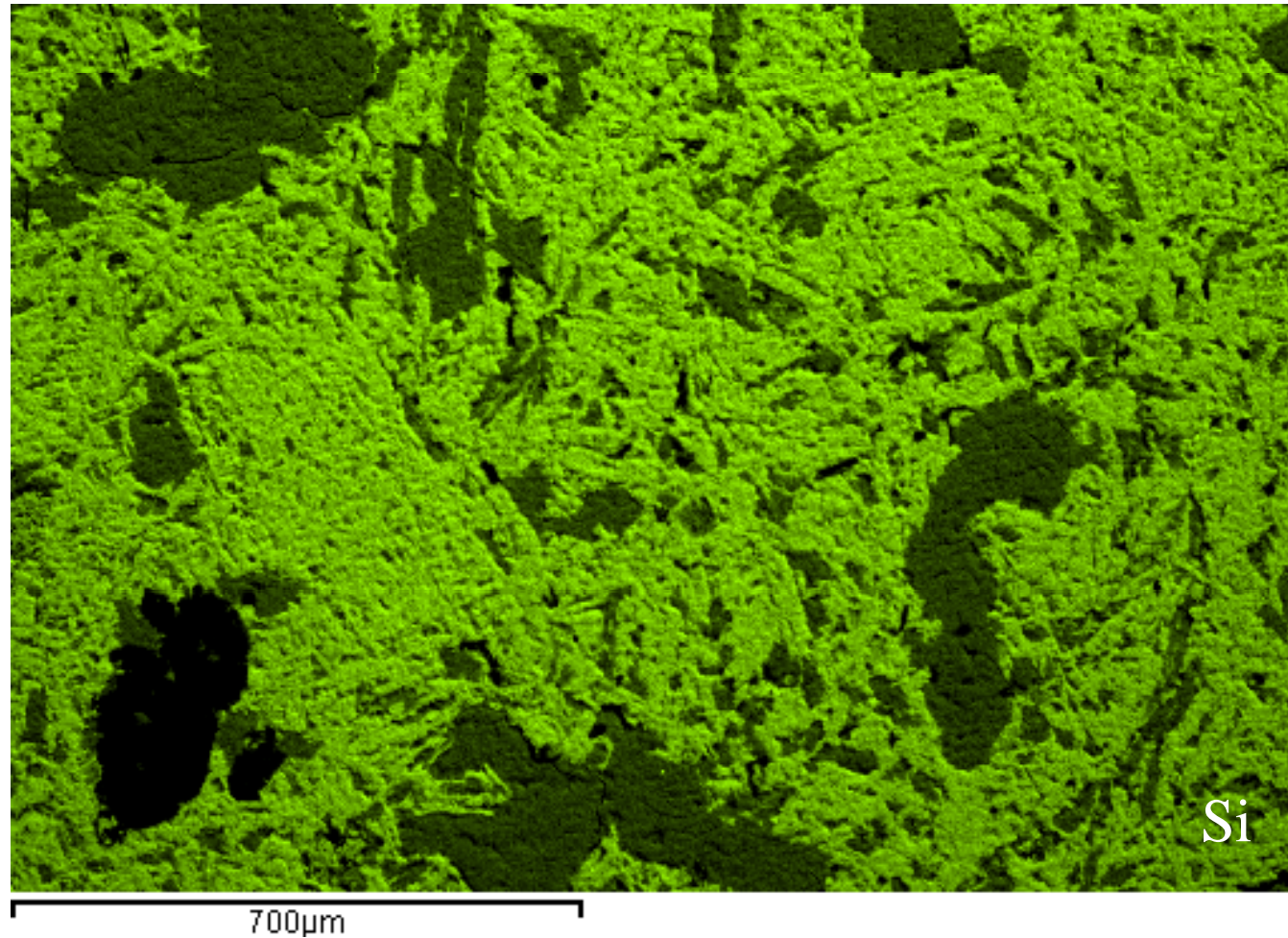
Variable Pressure



Basalt - uncoated

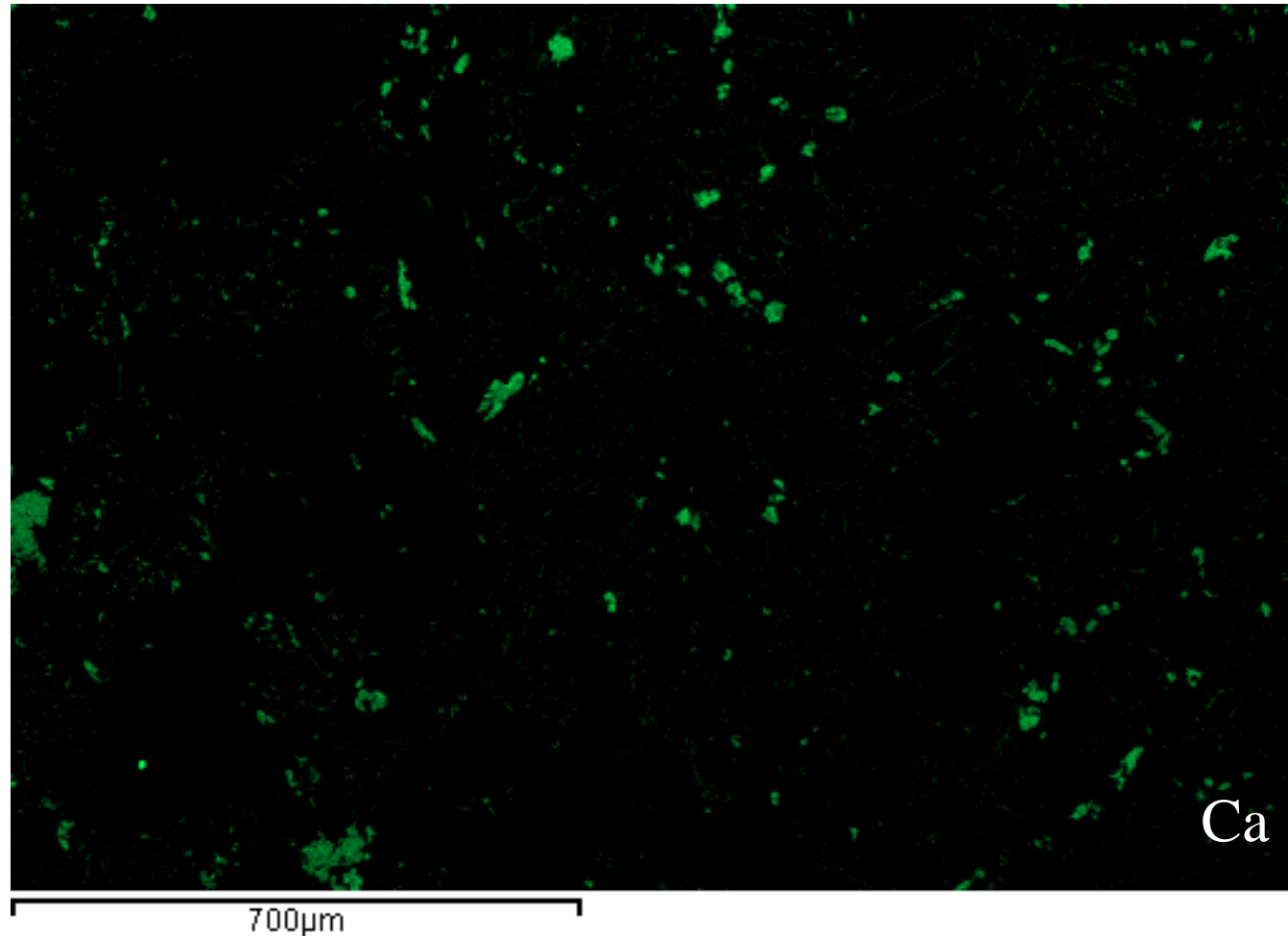
Hitachi High-Technologies Europe GmbH

X-ray mapping



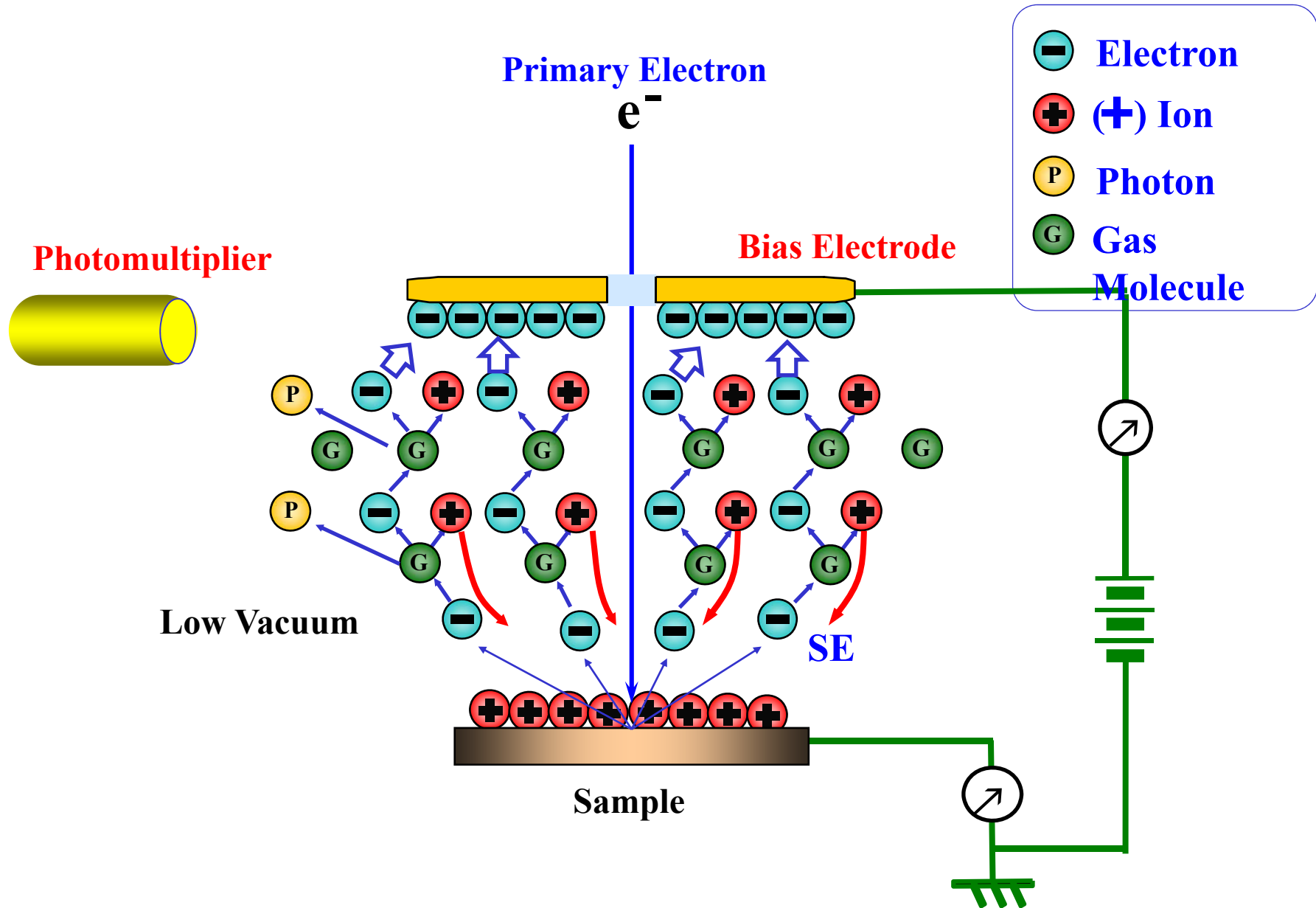
77850cps, 38min., VP=50Pa, 60nA

X-ray mapping



77850cps, 38min., VP=50Pa, 60nA

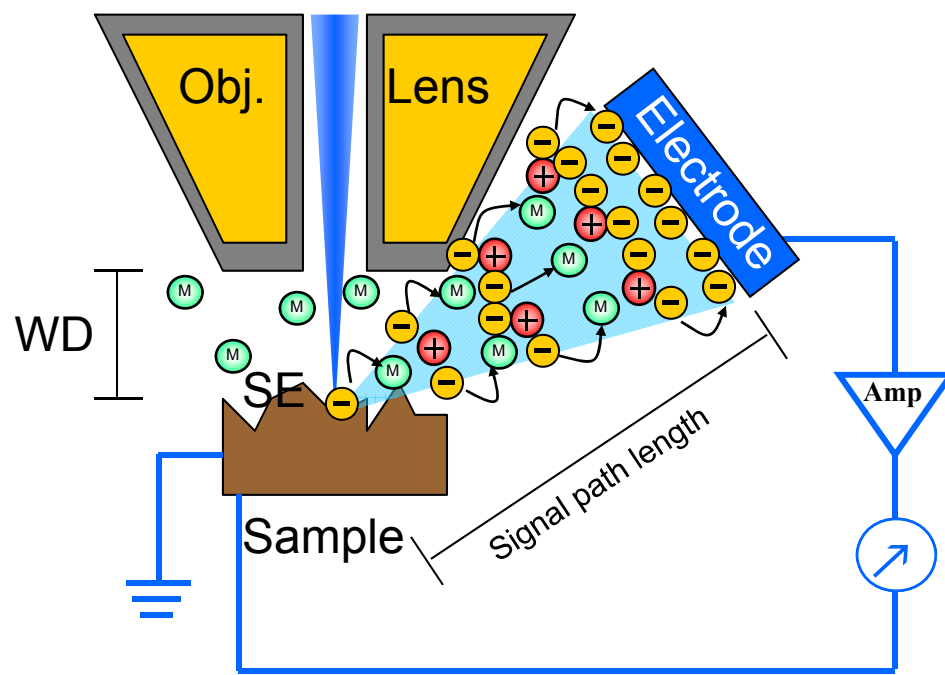
Variable Pressure SEM



SE Imaging at Low Chamber Vacuum



Application: Operation under low chamber vacuum.
High surface detail resolution especially for light elements

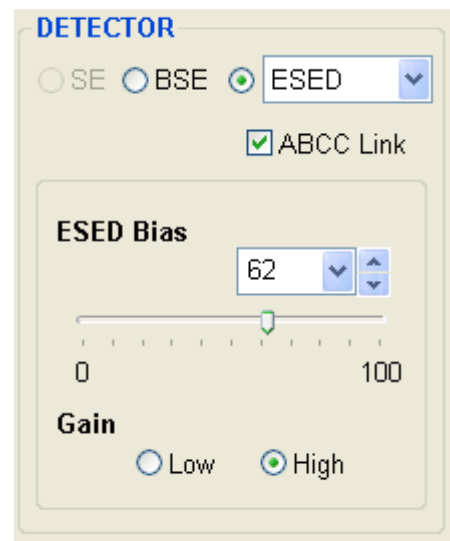


Secondary electrons (SE) ionize gas molecules above the sample surface. Electric collection field accelerates SE -> further ionization, avalanche effect.

Recordable current per image pixel is proportional to the number of created SE.

Working distance $WD <$ signal path length:

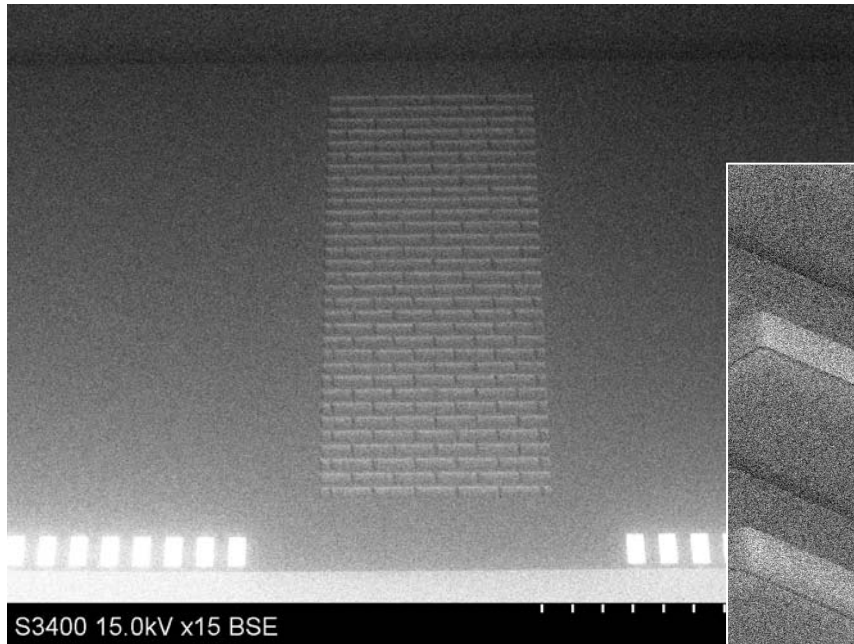
- high beam quality, less scattering at gas molecules
- large signal path length for efficient signal amplification



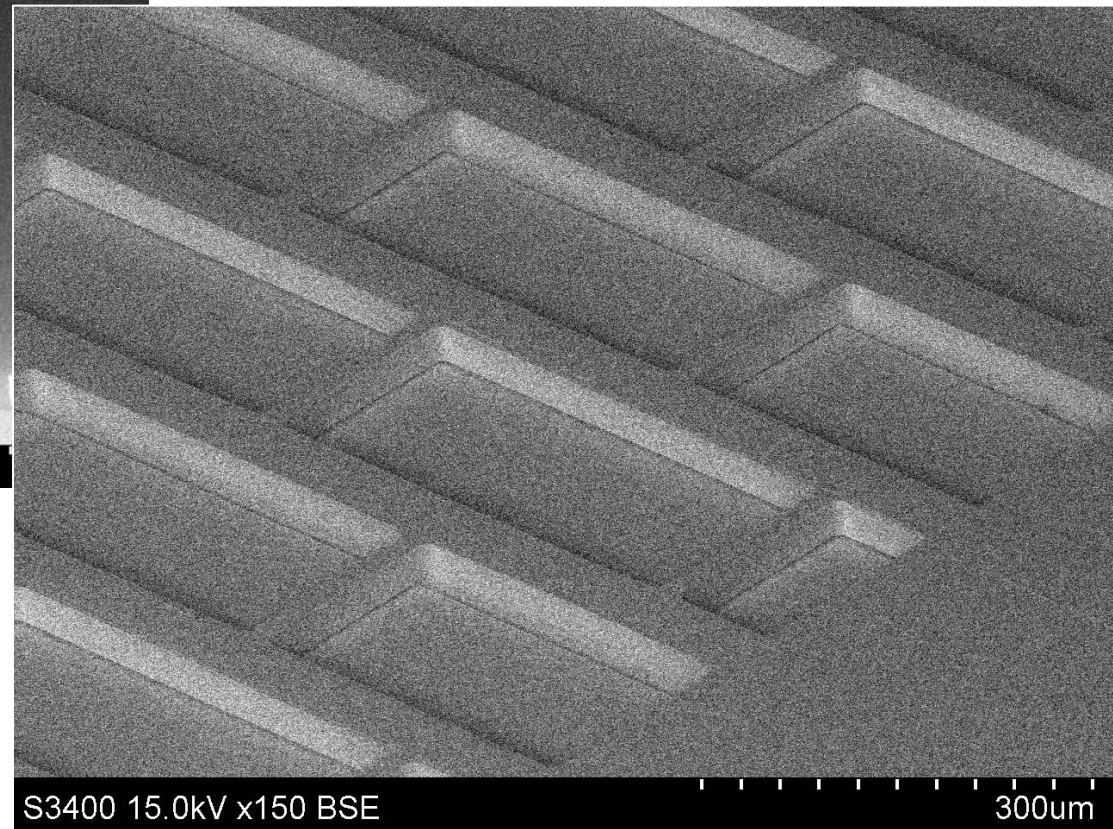
SE Imaging at Low Chamber Vacuum

Sample : Quartz (low atomic numbers)

BSE image



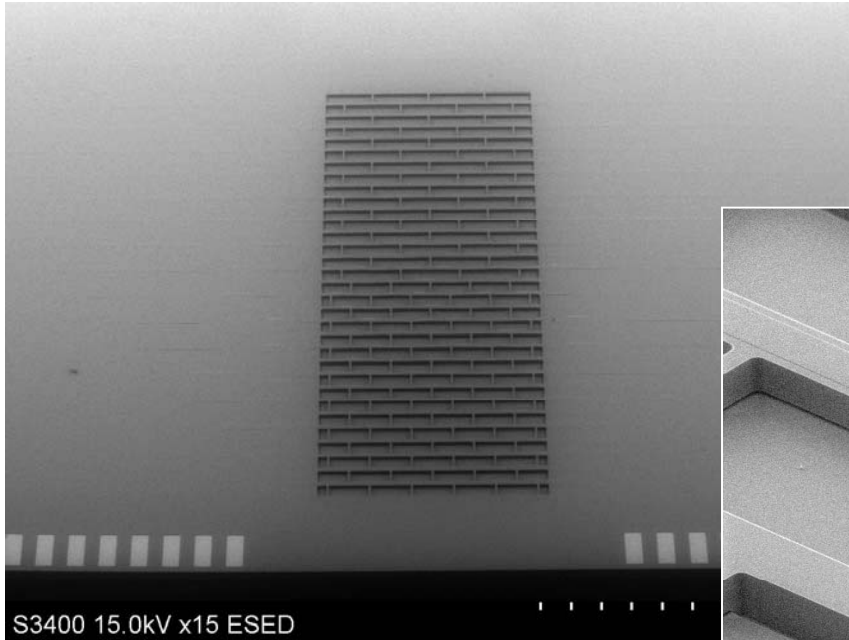
Chamber pressure: 60Pa
Vacc: 15kV



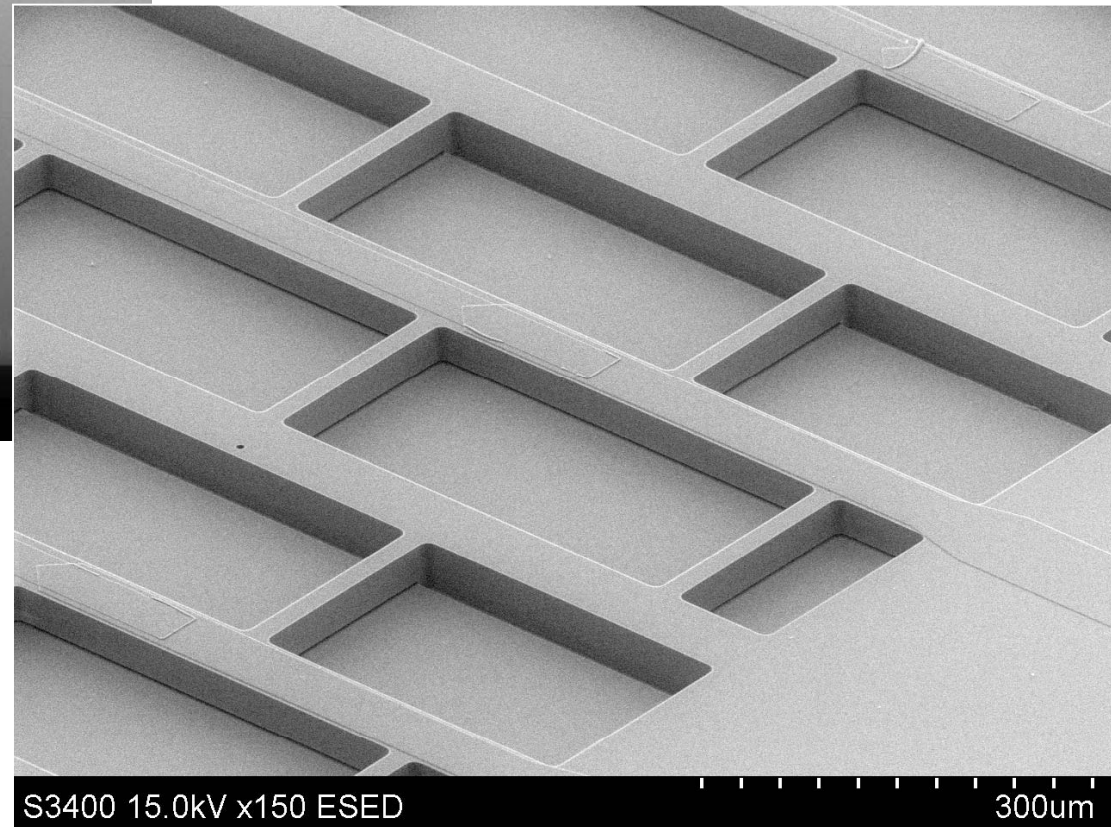
SE Imaging at Low Chamber Vacuum

Sample : Quartz (low atomic numbers)

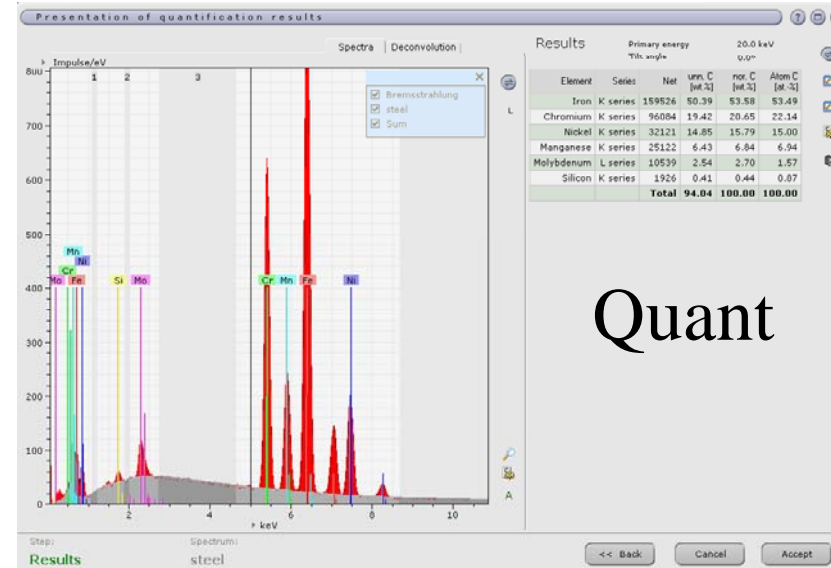
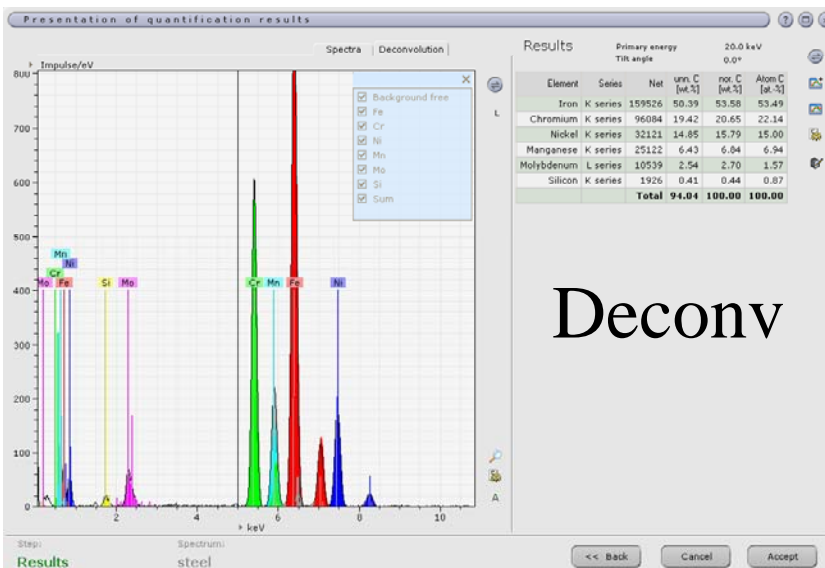
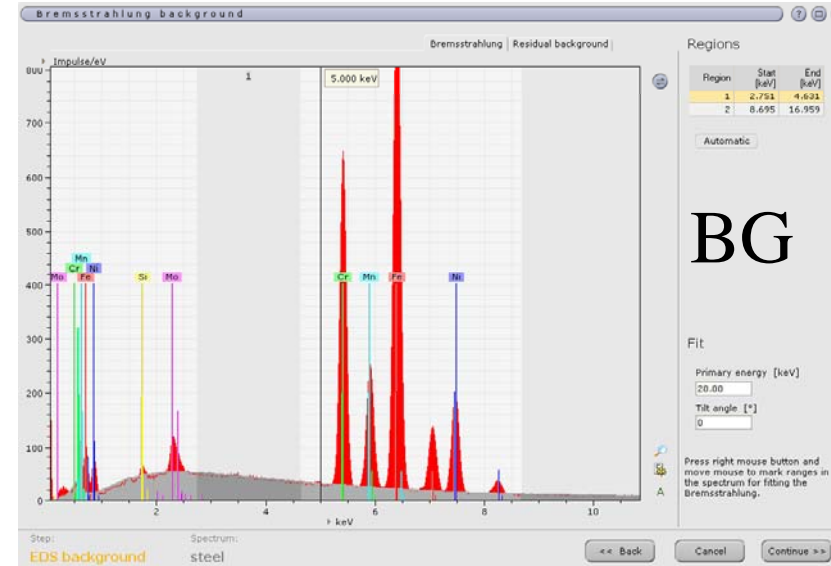
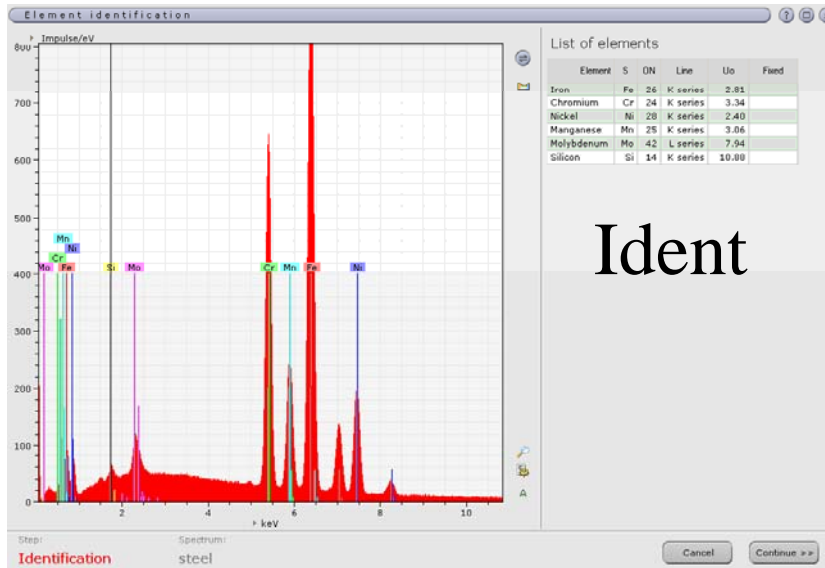
ESED image:
Many surface details
Good S/N ratio



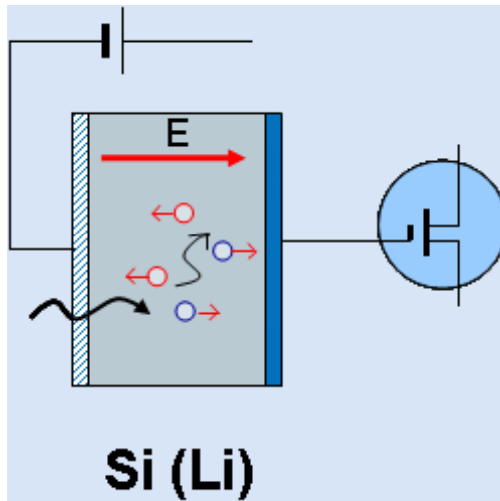
Chamber pressure: 60Pa
Vacc: 15kV



Quantification steps



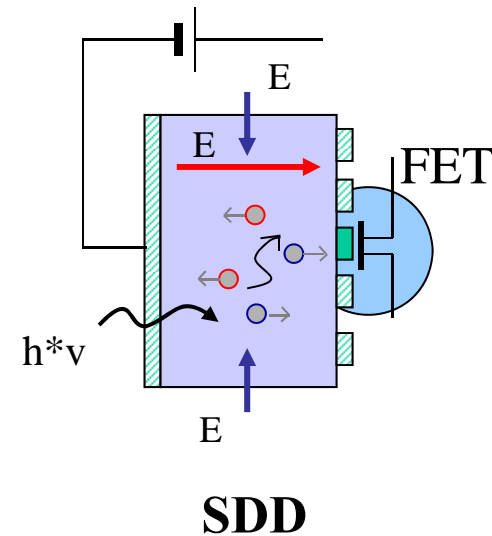
Si- based detector (schematic)



A Si(Li) is built on a bulk silicon semiconductor crystal which has an inert volume, drifted with Li

Charge carriers produced by incoming X-rays are swept to the anode which is the entire surface of the crystal

To reduce noise the detector crystals and the separate first stage amplifier (FET) need to be cooled at -180°C



100...120
fF !

The SDD is a semiconductor device with a greatly reduced anode spot and drift rings
The drift field guides the charge clouds to the designated anode spot
An integrated monolithically FET amplifies the signal
operating temperature (around -20°C) can easily be achieved by thermoelectric cooling (Peltier)

From LN2 cooled to SDD

- Why are Silicon Drift Detectors replacing LN₂ cooled Si(Li) systems ?
 - No liquid nitrogen
 - High countrates
 - Good resolution at high countrates
 - Small, less risk for vibration or acoustic disturbance
- Lately also :
 - Resolution down to 123 eV
 - Detection down to Be
 - Countrates over 1.000.000 possible

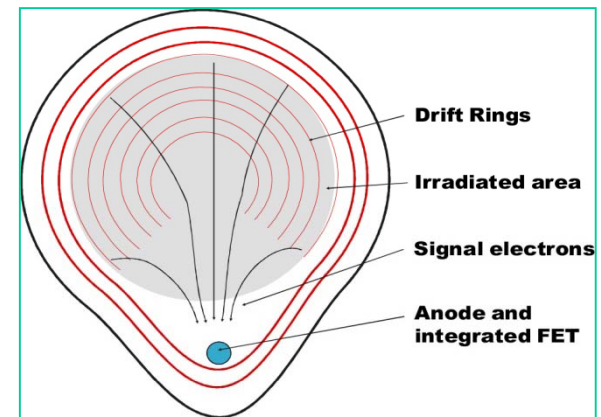
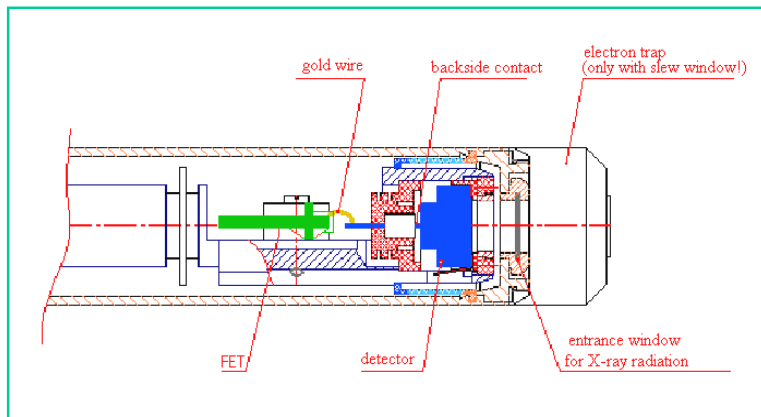
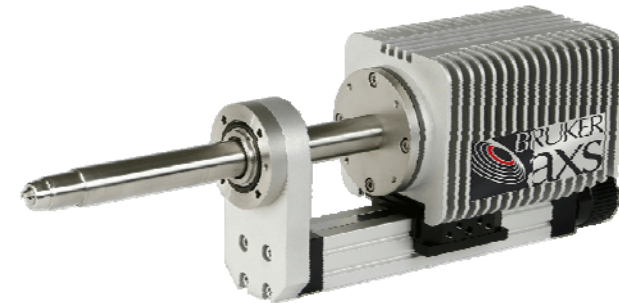
From LN2 cooled to SDD



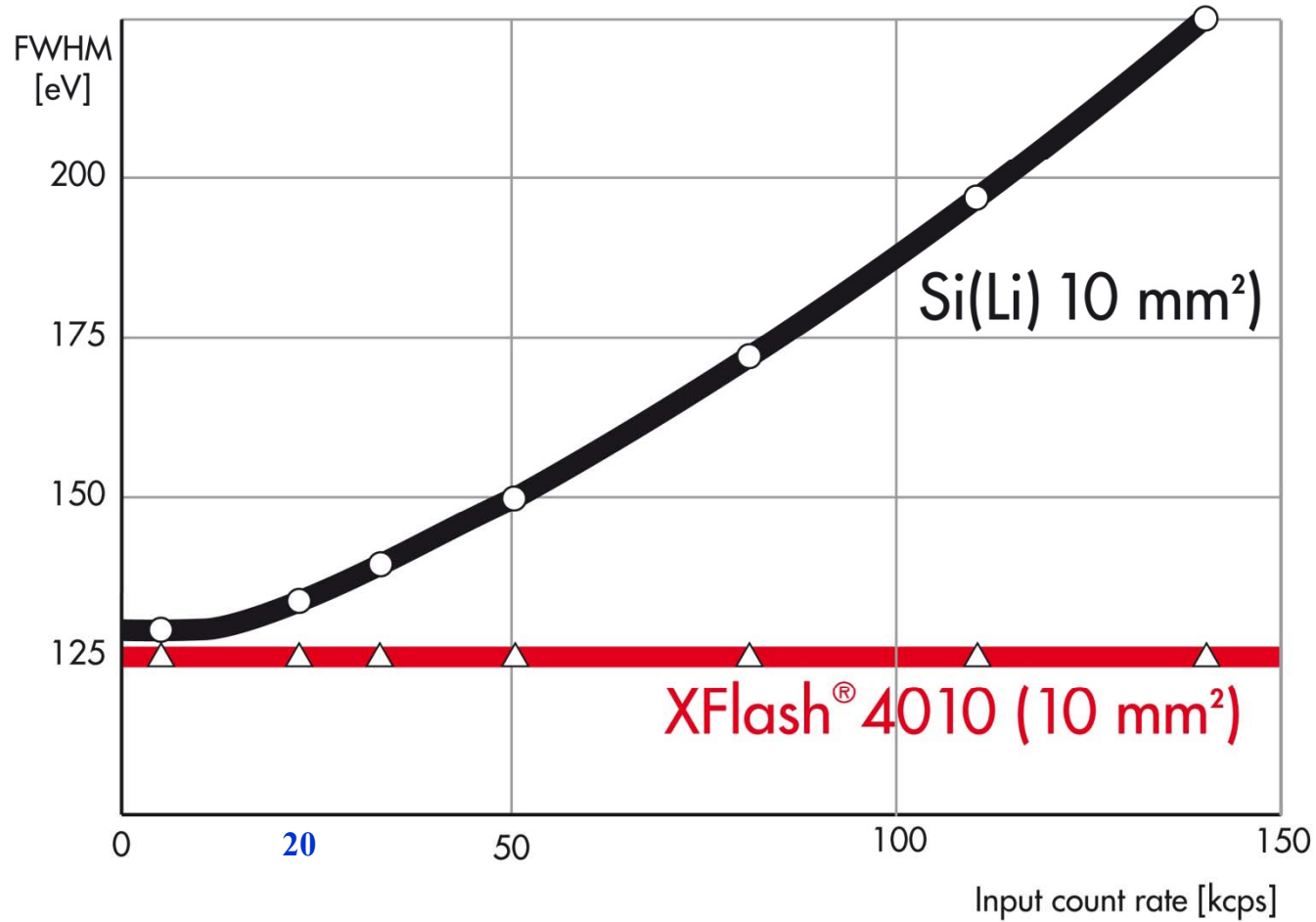
Low capacitance



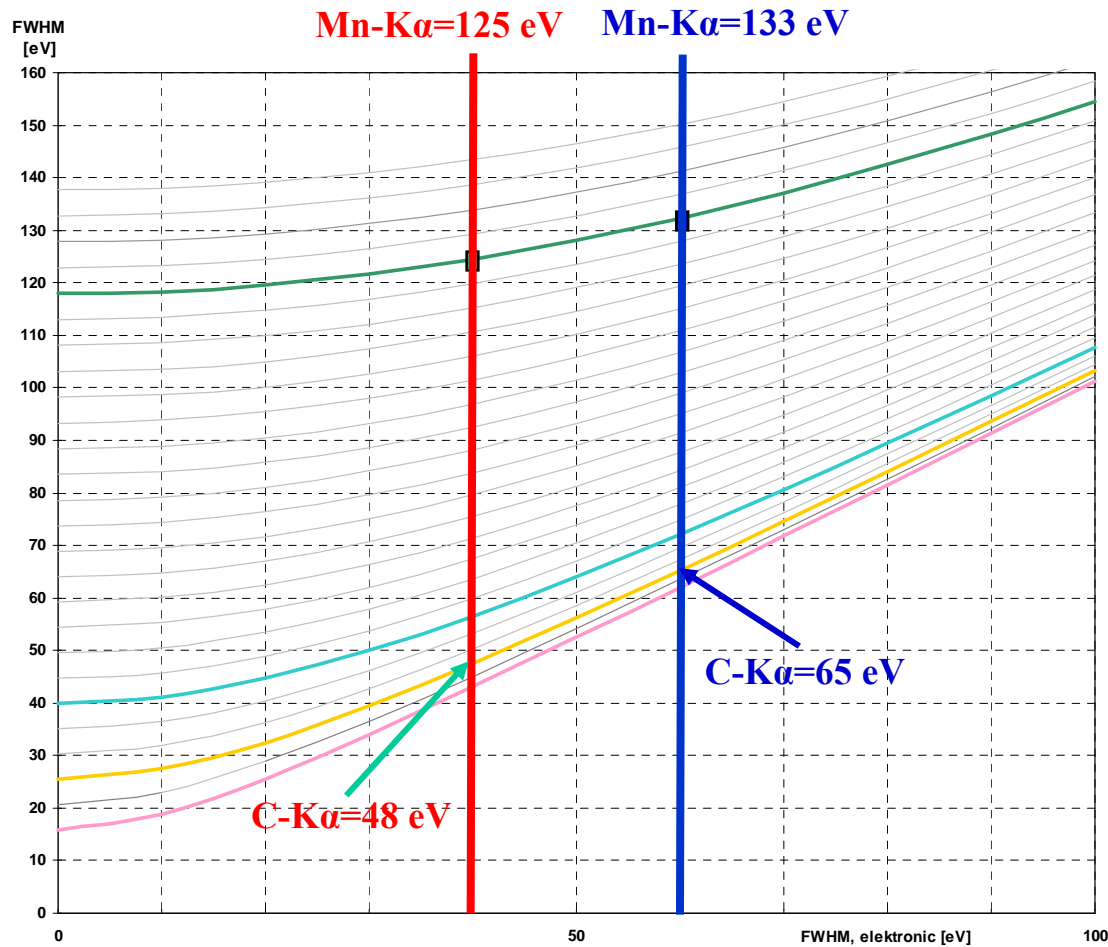
High speed



Resolution vs countrate



Resolution at low energies

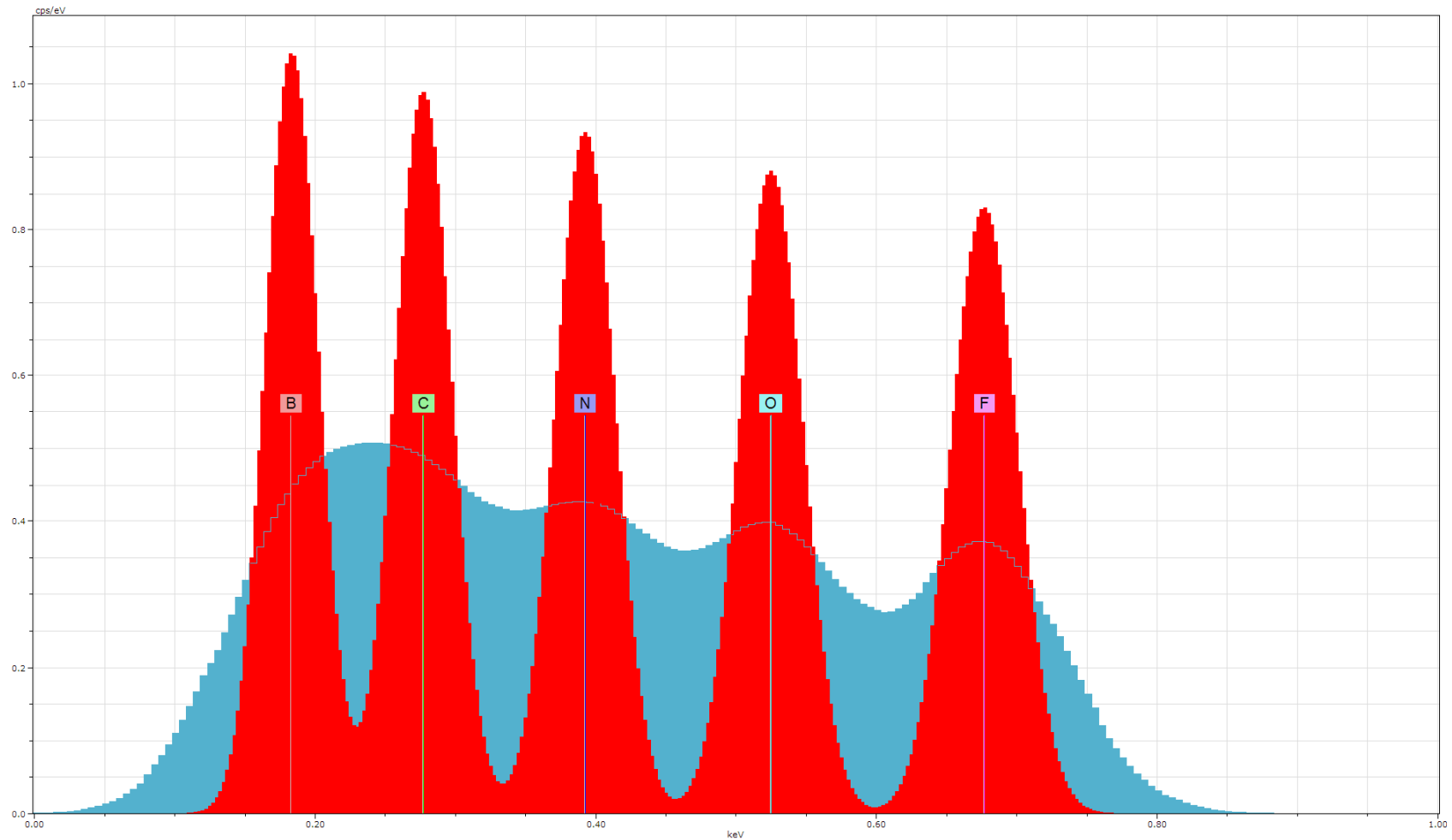


- 8eV at Mn-K α

- 17eV at C-K α

Spectra comparison 123 eV / 150 eV

@ 60.000 cps output



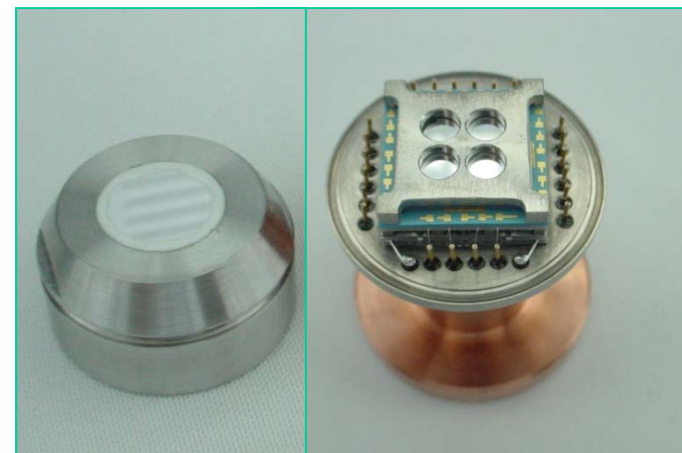
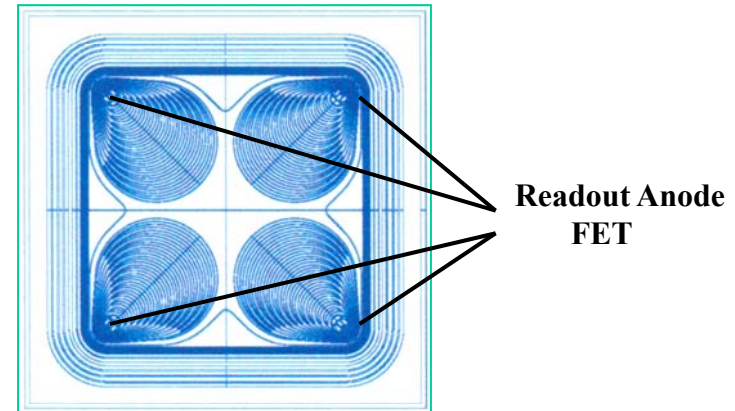
Dual Detector QUANTAX



Hitachi SU-1500
With dual XFlash QUANTAX

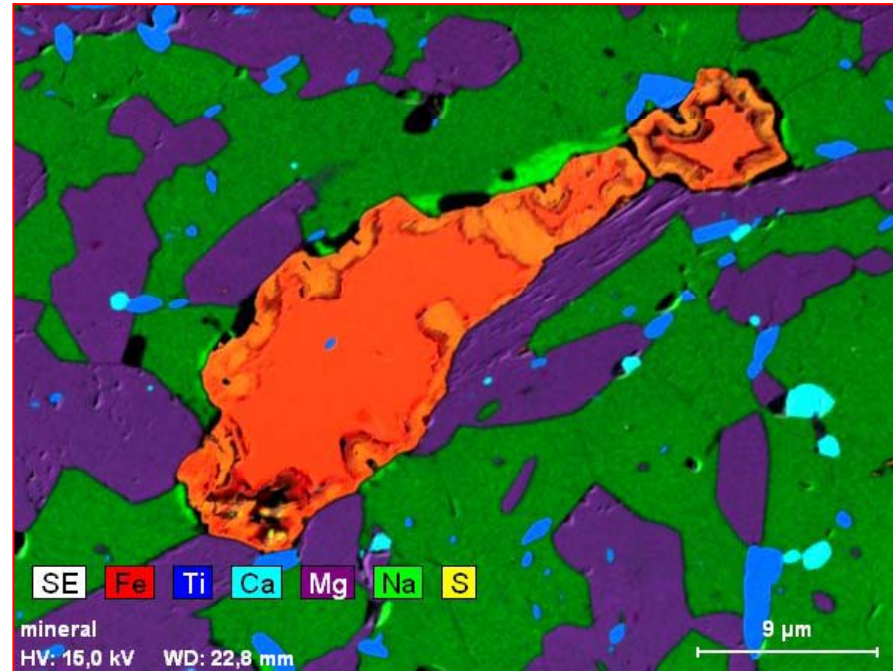
What about 4 x 10 mm² chips ?

- 4th SDD generation, Tear Drop Layout
- 40 mm² active area (4x10 mm²)
- Energy resolution: $\leq 123 - 133$ eV
- Detection from Boron (5) and up
- Max. input pulse rate: 3 000 000 cps
- Up to 50 times faster than 30 mm² Si(Li)
- Vibration-free, maintenance-free



Practical consequence of speed

- XFlash® QUAD 5040
Spectrometry mode
138 eV resolution
720,000 cps input
40% dead time
Acquisition time: 7 minutes
- Si(Li) detector (30 mm²)
138 eV resolution
20,000 cps input
60% dead time
Acquisition time: 6.25 hours
- Si(Li) takes **50 times longer**



- Mineralogical sample
 - 15 keV
 - 600 x 450 pixels

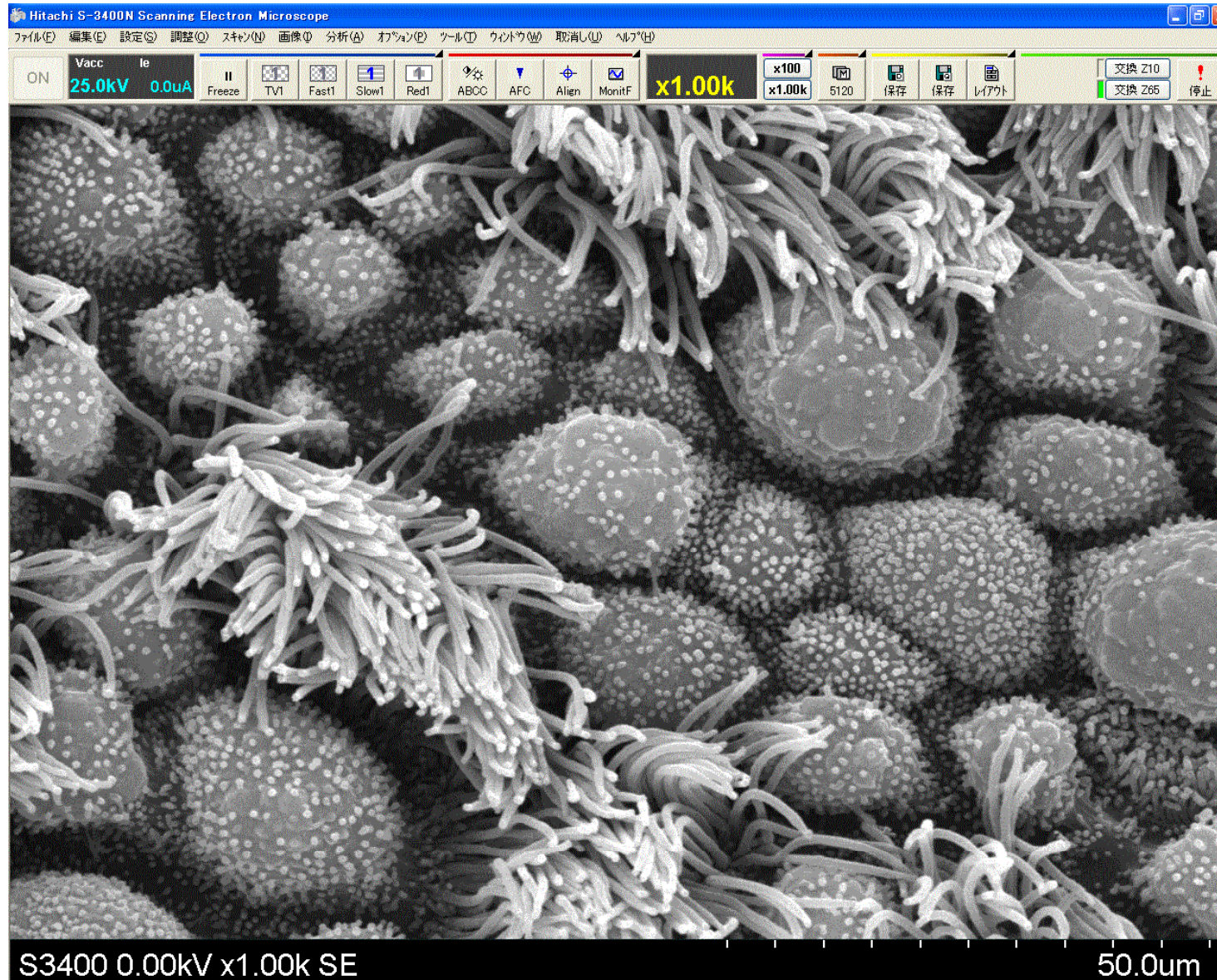
Thank you !

Spectral
Solutions

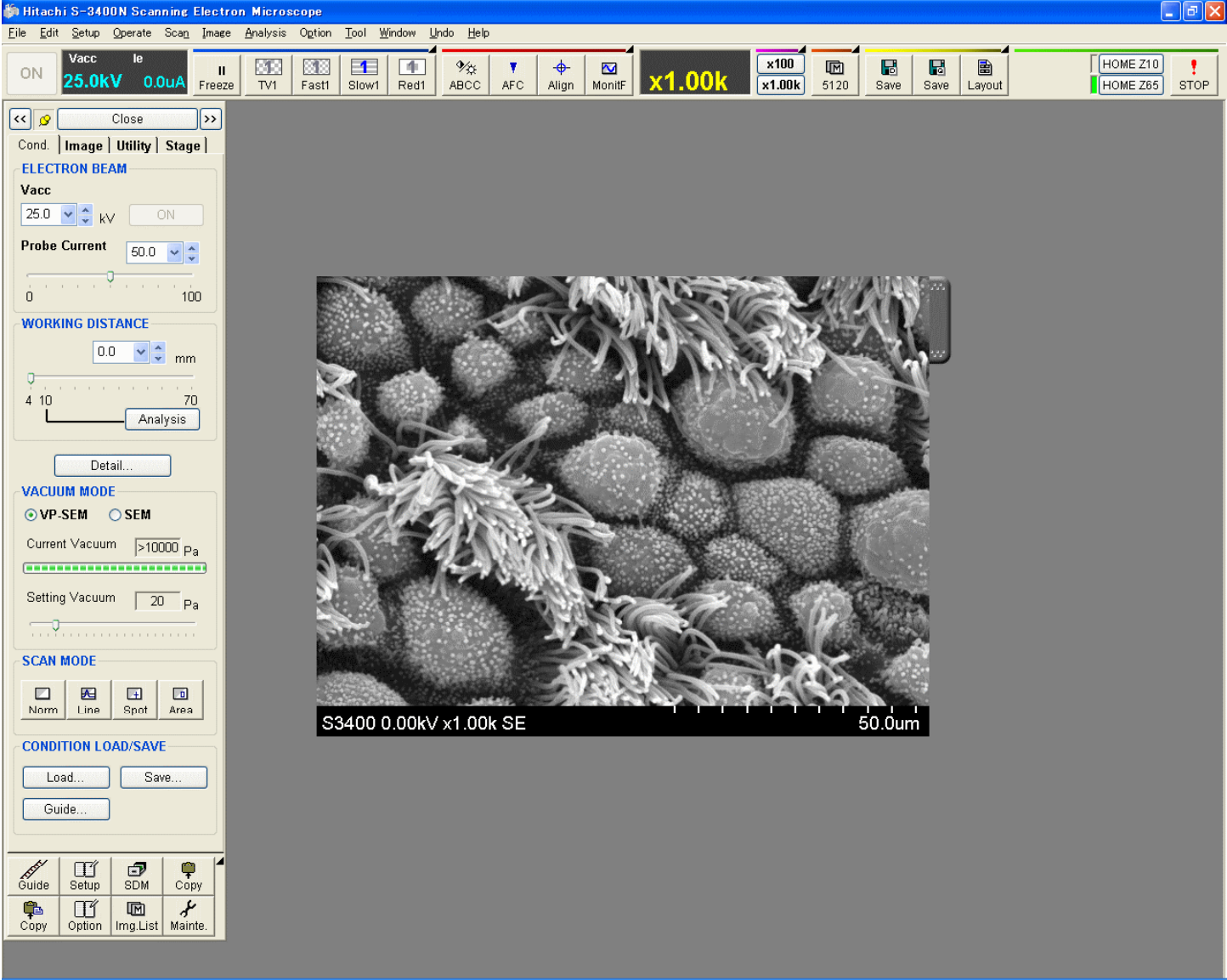


Hitachi SU-70

Display Mode – Full Screen



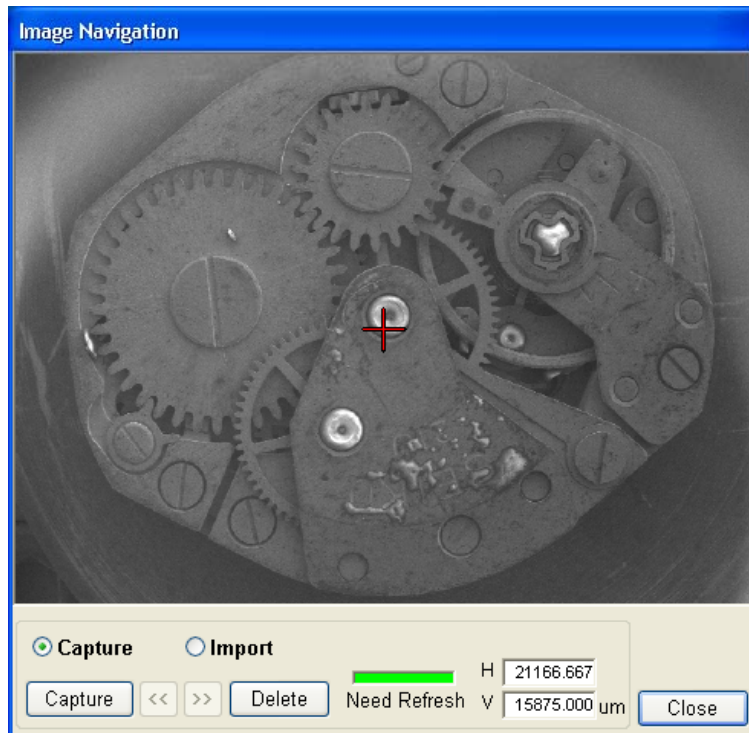
Display Mode - Standard



Sample Navigation

Navigation possible on

- Low-mag SEM images
- Imported Graphics (jpg, bmp, tif)
- Optical CCD-Camera-Images



Point of interest can be centered by mouse click or dragging.

The screenshot displays the Hitachi S-3700N Scanning Electron Microscope software interface. At the top, a menu bar includes options like 'ファイル(F)', '編集(E)', '設定(S)', '調整(O)', 'スキャン(N)', '画像(I)', '分析(A)', 'ワーク(W)', 'ツール(T)', 'ウィンドウ(W)', '元に戻す(R)', and 'ヘルプ(H)'. Below the menu is a control panel with various icons for 'ON/OFF', 'Vacc', 'le', 'Freeze', 'TVI', 'Slow1', 'Slow3', 'Red1', 'ABCC', 'AFC', 'Align', and 'MonitF'. The magnification is set to 'x20', with zoom levels 'x100' and 'x1.00k' also visible. The main display area is split into two windows. The left window, titled 'Image Navigation', shows a low-magnification overview of a sample with a blue rectangular region of interest. A yellow arrow labeled 'Click' points to a specific location within this region. Below this window are radio buttons for 'SEM画像', '外部画像', and 'カメラ映像', along with checkboxes for '表示' and 'カラー', and buttons for 'カメラ映像', '<<', '>>', 'クリア', 'アライメント', 'マーク', '保存...', and '閉じる'. The right window shows a high-magnification view of a gear-like structure with a yellow crosshair centered on the target location. The text 'FREEZE' is visible in the top left of this window. At the bottom of the right window, technical details '15.0kV x12 BSE3D' and a scale bar '4.00mm' are shown.

Click

Mouse-Click at desired target location moves the point to the screen center.

Navigation on Sample

As each image is stored with the stage coordinate of its recording site, a return to a previous observation site is possible at any time.



Image Management

SEM Data Manager allows post-processing (measurement, labeling, filtering) and administration of recorded images.

